

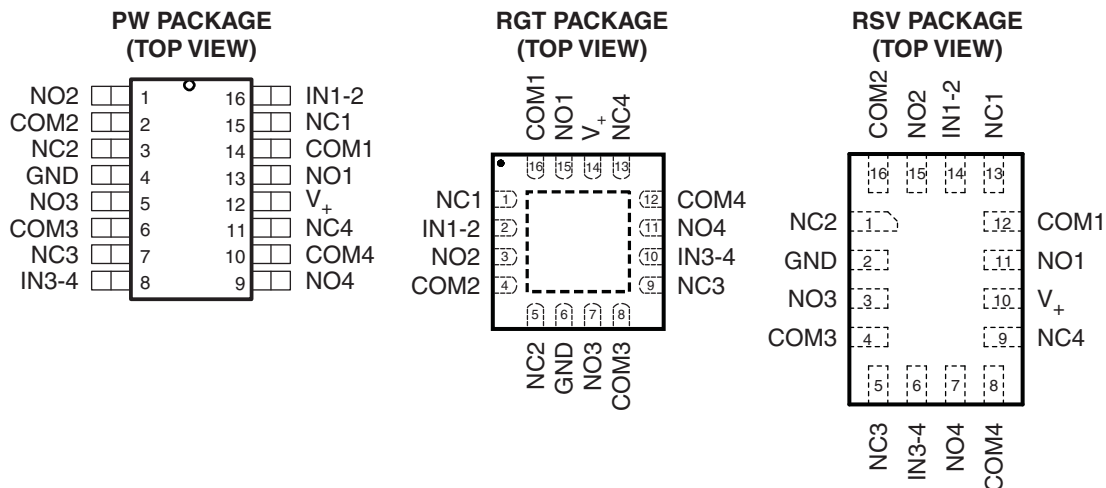
## 0.45-Ω QUAD SPDT ANALOG SWITCH QUAD-CHANNEL 2:1 MULTIPLEXER/DEMULTIPLEXER WITH TWO CONTROLS

### FEATURES

- Specified Break-Before-Make Switching
- Low ON-State Resistance (<0.5 Ω)
- Control Inputs Are 1.8-V Logic Compatible
- Low Charge Injection
- Excellent ON-State Resistance Matching
- Low Total Harmonic Distortion (THD)
- 1.65-V to 4.3-V Single-Supply Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Performance Tested Per JESD 22
  - 2000-V Human-Body Model (A114-B, Class II)
  - 1000-V Charged-Device Model (C101)

### APPLICATIONS

- Cell Phones
- PDAs
- Portable Instrumentation
- Audio and Video Signal Routing
- Low-Voltage Data-Acquisition Systems
- Communication Circuits
- Modems
- Hard Drives
- Computer Peripherals
- Wireless Terminals and Peripherals



### DESCRIPTION/ORDERING INFORMATION

The TS3A44159 is a quad single-pole double-throw (SPDT) analog switch with two control inputs, which is designed to operate from 1.65 V to 4.3 V. This device is also known as a dual double-pole double-throw (DPDT) configuration. It offers low ON-state resistance and excellent ON-state resistance matching with the break-before-make feature, to prevent signal distortion during the transferring of a signal from one channel to another. The device has an excellent total harmonic distortion (THD) performance and consumes very low power. These features make this device suitable for portable audio applications.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

**ORDERING INFORMATION**

| T <sub>A</sub> | PACKAGE <sup>(1)(2)</sup> |               | ORDERABLE PART NUMBER | TOP-SIDE MARKING |
|----------------|---------------------------|---------------|-----------------------|------------------|
| -40°C to 85°C  | RGT – QFN                 | Tape and reel | TS3A44159RGTR         | ZWH              |
|                | RSV – QFN                 | Tape and reel | TS3A44159RSVR         | ZWH              |
|                | PW – TSSOP                | Tape and reel | TS3A44159PWR          | YC4159           |

- (1) Package drawings, thermal data, and symbolization are available at [www.ti.com/packaging](http://www.ti.com/packaging).
- (2) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at [www.ti.com](http://www.ti.com).

**SUMMARY OF CHARACTERISTICS<sup>(1)</sup>**

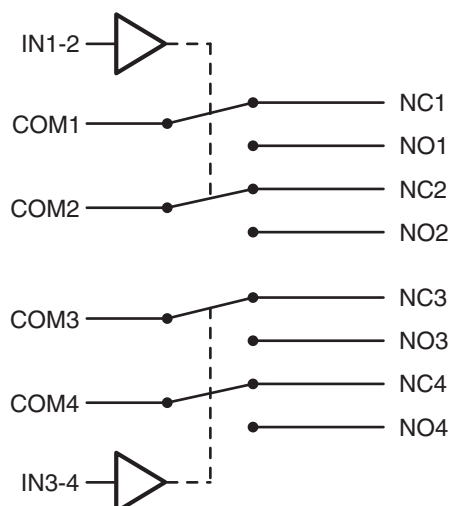
| Configuration  | Quad 2:1 Multiplexer/Demultiplexer<br>(4 × SPDT or 2 × DPDT) |
|--|--|
| Number of channels   | 4  |
| ON-state resistance (r <sub>on</sub> )                     | 0.45 Ω (max)   |
| ON-state resistance match (Δr <sub>on</sub> )              | 0.07 Ω (max)   |
| ON-state resistance flatness (r <sub>ON(flat)</sub> )      | 0.1 Ω (max)  |
| Turn-on/turn-off time (t <sub>ON</sub> /t <sub>OFF</sub> ) | 23 ns/32 ns  |
| Break-before-make time (t <sub>BBM</sub> )                 | 30 ns  |
| Charge injection (Q <sub>C</sub> )                         | 139 pC   |
| Bandwidth (BW)   | 35 MHz   |
| OFF isolation (O <sub>ISO</sub> )                          | -71 dB   |
| Crosstalk (X <sub>TALK</sub> )                             | -73 dB   |
| Total harmonic distortion (THD)                            | 0.003%   |
| Power-supply current (I <sub>+</sub> )                     | 0.4 μA   |
| Package option   | 16-pin QFN   |

(1) V<sub>+</sub> = 4.3 V, T<sub>A</sub> = 25°C

**FUNCTION TABLE**

| IN | NC TO COM,<br>COM TO NC | NO TO COM,<br>COM TO NO |
|----|-------------------------|-------------------------|
| L  | ON                      | OFF                     |
| H  | OFF                     | ON                      |

**LOGIC DIAGRAM**



**ABSOLUTE MAXIMUM RATINGS**<sup>(1)(2)</sup>

over operating free-air temperature range (unless otherwise noted)

|                                   |   | MIN                           | MAX         | UNIT |
|-----------------------------------|---|-------------------------------|-------------|------|
| $V_+$                             | Supply voltage range <sup>(3)</sup>           | –0.5                          | 4.6         | V    |
| $V_{NC}$<br>$V_{NO}$<br>$V_{COM}$ | Analog voltage range <sup>(3)(4)(5)</sup>     | –0.5                          | $V_+ + 0.5$ | V    |
| $I_K$                             | Analog port diode current                     | $V_{NC}, V_{NO}, V_{COM} < 0$ |             | mA   |
| $I_{NC}$<br>$I_{NO}$<br>$I_{COM}$ | ON-state switch current                       | –200                          | 200         | mA   |
|                                   | ON-state peak switch current <sup>(6)</sup>   | –400                          | 400         |      |
| $V_I$                             | Digital input voltage range                   | –0.5                          | 4.6         | V    |
| $I_{IK}$                          | Digital input clamp current <sup>(3)(4)</sup> | $V_I < 0$                     |             | mA   |
| $I_+$                             | Continuous current through $V_+$              |                               | 100         | mA   |
| $I_{GND}$                         | Continuous current through GND                | –100                          |             | mA   |
| $\theta_{JA}$                     | Package thermal impedance <sup>(7)</sup>      | PW package                    |             | 108  |
|                                   |   | RGT package                   |             | TBD  |
|                                   |   | RSV package                   |             | TBD  |
| $T_{stg}$                         | Storage temperature range                     | –65                           | 150         | °C   |

- (1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied.
- (2) The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum
- (3) All voltages are with respect to ground, unless otherwise specified.
- (4) The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
- (5) This value is limited to 4.6 V maximum.
- (6) Pulse at 1-ms duration <10% duty cycle
- (7) The package thermal impedance is calculated in accordance with JESD 51-7.

**ELECTRICAL CHARACTERISTICS FOR 4.3-V SUPPLY<sup>(1)</sup>**T<sub>A</sub> = –40°C to 85°C (unless otherwise noted)

| PARAMETER  | SYMBOL  | TEST CONDITIONS  | T <sub>A</sub>                              | V <sub>+</sub> | MIN   | TYP  | MAX            | UNIT |
|--|---|--|---|----------------|-------|------|----------------|------|
| <b>Analog Switch</b>                                       |   |  |   |                |       |      |                |      |
| Analog signal range  | V <sub>COM</sub> ,<br>V <sub>NO</sub> , V <sub>NC</sub> |  |   |                | 0     |      | V <sub>+</sub> | V    |
| ON-state resistance  | r <sub>on</sub>   | V <sub>NO</sub> or V <sub>NC</sub> = 2.5 V,<br>I <sub>COM</sub> = –100 mA,   | Switch ON,<br>See <a href="#">Figure 16</a> | 25°C           | 4.3 V | 0.3  | 0.45           | Ω    |
|  |   |  |   | Full           |       | 0.5  |                |      |
| ON-state resistance match between channels                 | Δr <sub>on</sub>  | V <sub>NO</sub> or V <sub>NC</sub> = 2.5 V,<br>I <sub>COM</sub> = –100 mA,   | Switch ON,<br>See <a href="#">Figure 16</a> | 25°C           | 4.3 V | 0.05 | 0.07           | Ω    |
|  |   |  |   | Full           |       | 0.1  |                |      |
| ON-state resistance flatness                               | r <sub>on(flat)</sub>                                   | V <sub>NO</sub> or V <sub>NC</sub> = 1 V,<br>1.5 V, 2.5 V,<br>I <sub>COM</sub> = –100 mA,  | Switch ON,<br>See <a href="#">Figure 16</a> | 25°C           | 4.3 V | 0.02 | 0.1            | Ω    |
|  |   |  |   | Full           |       | 0.1  |                |      |
| NC, NO OFF leakage current                                 | I <sub>NO(OFF)</sub> ,<br>I <sub>NC(OFF)</sub>          | V <sub>NO</sub> or V <sub>NC</sub> = 0.3 V,<br>V <sub>COM</sub> = 3.0 V,<br>or<br>V <sub>NO</sub> or V <sub>NC</sub> = 3.0 V,<br>V <sub>COM</sub> = 0.3 V, | See <a href="#">Figure 17</a>               | 25°C           | 4.3 V | –20  | 5              | nA   |
|  |   |  |   | Full           |       | –90  | 90             |      |
| NC, NO ON leakage current                                  | I <sub>NO(ON)</sub> ,<br>I <sub>NC(ON)</sub>            | V <sub>NO</sub> or V <sub>NC</sub> = 0.3 V,<br>V <sub>COM</sub> = Open,<br>or<br>V <sub>NO</sub> or V <sub>NC</sub> = 3.0 V,<br>V <sub>COM</sub> = Open,   | See <a href="#">Figure 18</a>               | 25°C           | 4.3 V | –20  | 5              | nA   |
|  |   |  |   | Full           |       | –90  | 90             |      |
| COM ON leakage current                                     | I <sub>COM(ON)</sub>                                    | V <sub>NO</sub> or V <sub>NC</sub> = Open,<br>V <sub>COM</sub> = 0.3 V,<br>or<br>V <sub>NO</sub> or V <sub>NC</sub> = Open,<br>V <sub>COM</sub> = 3.0 V,   | See <a href="#">Figure 18</a>               | 25°C           | 4.3 V | –20  | 5              | nA   |
|  |   |  |   | Full           |       | –90  | 90             |      |
| <b>Digital Control Inputs (IN1-2, IN3-4)<sup>(2)</sup></b> |   |  |   |                |       |      |                |      |
| Input logic high   | V <sub>IH</sub>   |  | Full  | 4.3 V          | 1.5   |      | 4.3            | V    |
| Input logic low  | V <sub>IL</sub>   |  | Full  | 4.3 V          | 0     |      | 1              | V    |
| Input leakage current                                      | I <sub>IH</sub> , I <sub>IL</sub>                       | V <sub>IN</sub> = 3.6 V or 0   | 25°C  | 4.3 V          | 0.5   |      | 10             | nA   |
|  |   |  | Full  |                | 50    |      |                |      |

(1) The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum

(2) All unused digital inputs of the device must be held at V<sub>+</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

**ELECTRICAL CHARACTERISTICS FOR 4.3-V SUPPLY (continued)**
 $T_A = -40^{\circ}\text{C}$  to  $85^{\circ}\text{C}$  (unless otherwise noted)

| PARAMETER                 | SYMBOL                           | TEST CONDITIONS   | $T_A$ | $V_+$ | MIN | TYP   | MAX | UNIT          |
|---------------------------|----------------------------------|---|-------|-------|-----|-------|-----|---------------|
| <b>Dynamic</b>            |                                  |   |       |       |     |       |     |               |
| Turn-on time              | $t_{ON}$                         | $V_{COM} = V_+$ ,<br>$R_L = 50\ \Omega$ ,<br>$C_L = 35\ \text{pF}$                          | 25°C  | 4.3 V |     | 17    | 23  | ns            |
|                           |                                  |   | Full  |       |     | 25    |     |               |
| Turn-off time             | $t_{OFF}$                        | $V_{COM} = V_+$ ,<br>$R_L = 50\ \Omega$ ,<br>$C_L = 35\ \text{pF}$                          | 25°C  | 4.3 V |     | 12    | 32  | ns            |
|                           |                                  |   | Full  |       |     | 35    |     |               |
| Break-before-make time    | $t_{BBM}$                        | $V_{NC} = V_{NO} = V_+$ ,<br>$R_L = 50\ \Omega$ ,<br>$C_L = 35\ \text{pF}$                  | 25°C  | 4.3 V |     | 2     | 9   | ns            |
|                           |                                  |   | Full  |       |     | 1     | 35  |               |
| Charge injection          | $Q_C$                            | $V_{GEN} = 0$ ,<br>$R_{GEN} = 0$ ,<br>$C_L = 1\ \text{nF}$                                  | 25°C  | 4.3 V |     | 139   |     | pC            |
| NC, NO off capacitance    | $C_{NC(OFF)}$ ,<br>$C_{NO(OFF)}$ | $V_{NC}$ or $V_{NO} = V_+$ or<br>GND,<br>Switch OFF,  | 25°C  | 4.3 V |     | 50    |     | pF            |
| NC, NO ON capacitance     | $C_{NC(ON)}$ ,<br>$C_{NO(ON)}$   | $V_{NC}$ or $V_{NO} = V_+$ or<br>GND,<br>Switch OFF,  | 25°C  | 4.3 V |     | 160   |     | pF            |
| COM ON capacitance        | $C_{COM(ON)}$                    | $V_{COM} = V_+$ or GND,<br>Switch ON,   | 25°C  | 4.3 V |     | 160   |     | pF            |
| Digital input capacitance | $C_I$                            | $V_I = V_+$ or GND  | 25°C  | 4.3 V |     | 2.5   |     | pF            |
| Bandwidth                 | BW                               | $R_L = 50\ \Omega$ ,<br>Switch ON   | 25°C  | 4.3 V |     | 35    |     | MHz           |
| OFF isolation             | $O_{ISO}$                        | $R_L = 50\ \Omega$ ,<br>$f = 100\ \text{kHz}$ ,<br>Switch OFF                               | 25°C  | 4.3 V |     | -71   |     | dB            |
| Crosstalk                 | $X_{TALK}$                       | $R_L = 50\ \Omega$ ,<br>$f = 100\ \text{kHz}$ ,<br>Switch ON                                | 25°C  | 4.3 V |     | -73   |     | dB            |
| Total harmonic distortion | THD                              | $R_L = 600\ \Omega$ ,<br>$C_L = 50\ \text{pF}$ ,<br>$f = 20\ \text{Hz}$ to $20\ \text{kHz}$ | 25°C  | 4.3 V |     | 0.003 |     | %             |
| <b>Supply</b>             |                                  |   |       |       |     |       |     |               |
| Positive supply current   | $I_+$                            | $V_I = V_+$ or GND,<br>Switch ON or OFF   | 25°C  | 4.3 V |     | 0.15  | 0.4 | $\mu\text{A}$ |
|                           |                                  |   | Full  |       |     | 1.2   |     |               |

**ELECTRICAL CHARACTERISTICS FOR 3.3-V SUPPLY<sup>(1)</sup>**
 $V_+ = 3\text{ V to }3.6\text{ V}$ ,  $T_A = -40^\circ\text{C to }85^\circ\text{C}$  (unless otherwise noted)

| PARAMETER  | SYMBOL                     | TEST CONDITIONS  | $T_A$                                       | $V_+$ | MIN   | TYP  | MAX   | UNIT     |    |
|--|----------------------------|--|---|-------|-------|------|-------|----------|----|
| <b>Analog Switch</b>                                       |                            |  |   |       |       |      |       |          |    |
| Analog signal range  | $V_{COM}, V_{NO}, V_{NC}$  |  |   |       | 0     |      | $V_+$ | V        |    |
| ON-state resistance  | $r_{on}$                   | $V_{NO}$ or $V_{NC} = 2.0\text{ V}$ ,<br>$I_{COM} = -100\text{ mA}$ ,  | Switch ON,<br>See <a href="#">Figure 16</a> | 25°C  | 3 V   | 0.37 | 0.55  | $\Omega$ |    |
|  |                            |  |   | Full  |       | 0.6  |       |          |    |
| ON-state resistance match between channels                 | $\Delta r_{on}$            | $V_{NO}$ or $V_{NC} = 2.0\text{ V}$ , 0.8 V,<br>$I_{COM} = -100\text{ mA}$ ,   | Switch ON,<br>See <a href="#">Figure 16</a> | 25°C  | 3 V   | 0.06 | 0.07  | $\Omega$ |    |
|  |                            |  |   | Full  |       | 0.1  |       |          |    |
| ON-state resistance flatness                               | $r_{on(Flat)}$             | $V_{NO}$ or $V_{NC} = 2.0\text{ V}$ , 0.8 V<br>$I_{COM} = -100\text{ mA}$ ,  | Switch ON,<br>See <a href="#">Figure 16</a> | 25°C  | 3 V   | 0.05 | 0.1   | $\Omega$ |    |
|  |                            |  |   | Full  |       | 0.1  |       |          |    |
| NC, NO OFF leakage current                                 | $I_{NO(OFF)}, I_{NC(OFF)}$ | $V_{NO}$ or $V_{NC} = 0.3\text{ V}$ ,<br>$V_{COM} = 3.0\text{ V}$ ,<br>or<br>$V_{NO}$ or $V_{NC} = 3.0\text{ V}$ ,<br>$V_{COM} = 0.3\text{ V}$ , | See <a href="#">Figure 17</a>               | 25°C  | 3.6 V | -15  | 5     | 15       | nA |
|  |                            |  |   | Full  |       | -50  | 50    |          |    |
| NC, NO ON leakage current                                  | $I_{NO(ON)}, I_{NC(ON)}$   | $V_{NO}$ or $V_{NC} = 0.3\text{ V}$ ,<br>$V_{COM} = \text{Open}$ ,<br>or<br>$V_{NO}$ or $V_{NC} = 3.0\text{ V}$ ,<br>$V_{COM} = \text{Open}$ ,   | See <a href="#">Figure 18</a>               | 25°C  | 3.6 V | -15  | 5     | 15       | nA |
|  |                            |  |   | Full  |       | -50  | 50    |          |    |
| COM ON leakage current                                     | $I_{COM(ON)}$              | $V_{NO}$ or $V_{NC} = \text{Open}$ ,<br>$V_{COM} = 0.3\text{ V}$ ,<br>or<br>$V_{NO}$ or $V_{NC} = \text{Open}$ ,<br>$V_{COM} = 3.0\text{ V}$ ,   | See <a href="#">Figure 18</a>               | 25°C  | 3.6 V | -15  | 5     | 15       | nA |
|  |                            |  |   | Full  |       | -50  | 50    |          |    |
| <b>Digital Control Inputs (IN1-2, IN3-4)<sup>(2)</sup></b> |                            |  |   |       |       |      |       |          |    |
| Input logic high   | $V_{IH}$                   |  | Full  |       | 1.25  |      | 4.3   | V        |    |
| Input logic low  | $V_{IL}$                   |  | Full  |       | 0     |      | 0.8   | V        |    |
| Input leakage current                                      | $I_{IH}, I_{IL}$           | $V_{IN} = 3.6\text{ V or }0$   | 25°C  | 3.6 V | 0.5   |      | 10    | nA       |    |
|  |                            |  | Full  |       | 50    |      |       |          |    |

(1) The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum

(2) All unused digital inputs of the device must be held at  $V_+$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

**ELECTRICAL CHARACTERISTICS FOR 3.3-V SUPPLY (continued)**
 $V_+ = 3\text{ V to }3.6\text{ V}$ ,  $T_A = -40^\circ\text{C to }85^\circ\text{C}$  (unless otherwise noted)

| PARAMETER                 | SYMBOL                           | TEST CONDITIONS  | $T_A$ | $V_+$        | MIN   | TYP   | MAX | UNIT          |
|---------------------------|----------------------------------|--|-------|--------------|-------|-------|-----|---------------|
| <b>Dynamic</b>            |                                  |  |       |              |       |       |     |               |
| Turn-on time              | $t_{ON}$                         | $V_{COM} = V_+$ ,<br>$R_L = 50\ \Omega$ ,<br>$C_L = 35\text{ pF}$                      | 25°C  | 3 V          | 20    | 38    | 40  | ns            |
|                           |                                  |  | Full  | 3 V to 3.6 V |       |       |     |               |
| Turn-off time             | $t_{OFF}$                        | $V_{COM} = V_+$ ,<br>$R_L = 50\ \Omega$ ,<br>$C_L = 35\text{ pF}$                      | 25°C  | 3 V          | 14    | 34    | 35  | ns            |
|                           |                                  |  | Full  | 3 V to 3.6 V |       |       |     |               |
| Break-before-make time    | $t_{BBM}$                        | $V_{NC} = V_{NO} = V_+$ ,<br>$R_L = 50\ \Omega$ ,<br>$C_L = 35\text{ pF}$              | 25°C  | 3 V          | 3     | 11    | 35  | ns            |
|                           |                                  |  | Full  | 3 V to 3.6 V | 2     |       | 55  |               |
| Charge injection          | $Q_C$                            | $V_{GEN} = 0$ ,<br>$R_{GEN} = 0$ ,<br>$C_L = 1\text{ nF}$                              | 25°C  | 3 V          |       | 109   |     | pC            |
| NC, NO OFF capacitance    | $C_{NC(OFF)}$ ,<br>$C_{NO(OFF)}$ | $V_{NC}$ or $V_{NO} = V_+$ or GND,<br>Switch OFF,<br>See <a href="#">Figure 19</a>     | 25°C  | 3 V          |       | 51    |     | pF            |
| NC, NO ON capacitance     | $C_{NC(ON)}$ ,<br>$C_{NO(ON)}$   | $V_{NC}$ or $V_{NO} = V_+$ or GND,<br>Switch OFF,<br>See <a href="#">Figure 19</a>     | 25°C  | 3 V          |       | 162   |     | pF            |
| COM ON capacitance        | $C_{COM(ON)}$                    | $V_{COM} = V_+$ or GND,<br>Switch ON,<br>See <a href="#">Figure 19</a>                 | 25°C  | 3 V          |       | 162   |     | pF            |
| Digital input capacitance | $C_I$                            | $V_I = V_+$ or GND   | 25°C  | 3 V          |       | 2.5   |     | pF            |
| Bandwidth                 | BW                               | $R_L = 50\ \Omega$ ,<br>Switch ON  | 25°C  | 3 V          |       | 35    |     | MHz           |
| OFF isolation             | $O_{ISO}$                        | $R_L = 50\ \Omega$ ,<br>$f = 100\text{ kHz}$ ,<br>Switch OFF                           | 25°C  | 3 V          |       | -71   |     | dB            |
| Crosstalk                 | $X_{TALK}$                       | $R_L = 50\ \Omega$ ,<br>$f = 100\text{ kHz}$ ,<br>Switch ON                            | 25°C  | 3 V          |       | -73   |     | dB            |
| Total harmonic distortion | THD                              | $R_L = 600\ \Omega$ ,<br>$C_L = 50\text{ pF}$ ,<br>$f = 20\text{ Hz to }20\text{ kHz}$ | 25°C  | 3 V          |       | 0.003 |     | %             |
| <b>Supply</b>             |                                  |  |       |              |       |       |     |               |
| Positive supply current   | $I_+$                            | $V_I = V_+$ or GND,<br>Switch ON or OFF  | 25°C  | 3.6 V        | 0.015 | 0.2   | 0.7 | $\mu\text{A}$ |
|                           |                                  |  | Full  |              |       |       |     |               |

**ELECTRICAL CHARACTERISTICS FOR 2.5-V SUPPLY<sup>(1)</sup>**
 $V_+ = 2.3 \text{ V to } 2.7 \text{ V}$ ,  $T_A = -40^\circ\text{C to } 85^\circ\text{C}$  (unless otherwise noted)

| PARAMETER  | SYMBOL                     | TEST CONDITIONS   | $T_A$ | $V_+$ | MIN | TYP   | MAX   | UNIT     |    |
|--|----------------------------|---|-------|-------|-----|-------|-------|----------|----|
| <b>Analog Switch</b>                                       |                            |   |       |       |     |       |       |          |    |
| Analog signal range  | $V_{COM}, V_{NO}, V_{NC}$  |   |       |       | 0   |       | $V_+$ | V        |    |
| ON-state resistance  | $r_{on}$                   | $V_{NO}$ or $V_{NC} = 1.8 \text{ V}$ ,<br>$I_{COM} = -100 \text{ mA}$ ,<br>Switch ON,<br>See <a href="#">Figure 16</a>  | 25°C  | 2.3 V |     | 0.45  | 0.6   | $\Omega$ |    |
|  |                            |   | Full  |       |     |       | 0.7   |          |    |
| ON-state resistance match between channels                 | $\Delta r_{on}$            | $V_{NO}$ or $V_{NC} = 1.8 \text{ V}, 0.8 \text{ V}$ ,<br>$I_{COM} = -100 \text{ mA}$ ,<br>Switch ON,<br>See <a href="#">Figure 16</a>   | 25°C  | 2.3 V |     | 0.045 | 0.07  | $\Omega$ |    |
|  |                            |   | Full  |       |     |       | 0.1   |          |    |
| ON-state resistance flatness                               | $r_{on(Flat)}$             | $V_{NO}$ or $V_{NC} = 1.8 \text{ V}, 0.8 \text{ V}$<br>$I_{COM} = -100 \text{ mA}$ ,<br>Switch ON,<br>See <a href="#">Figure 16</a>   | 25°C  | 2.3 V |     | 0.06  | 0.15  | $\Omega$ |    |
|  |                            |   | Full  |       |     |       | 0.2   |          |    |
| NC, NO OFF leakage current                                 | $I_{NO(OFF)}, I_{NC(OFF)}$ | $V_{NO}$ or $V_{NC} = 0.3 \text{ V}$ ,<br>$V_{COM} = 2.3 \text{ V}$ ,<br>or<br>$V_{NO}$ or $V_{NC} = 2.3 \text{ V}$ ,<br>$V_{COM} = 0.3 \text{ V}$ ,<br>See <a href="#">Figure 17</a> | 25°C  | 2.7 V |     | -10   | 0.5   | 10       | nA |
|  |                            |   | Full  |       |     |       | -20   | 20       |    |
| NC, NO ON leakage current                                  | $I_{NO(ON)}, I_{NC(ON)}$   | $V_{NO}$ or $V_{NC} = 0.3 \text{ V}$ ,<br>$V_{COM} = \text{Open}$ ,<br>or<br>$V_{NO}$ or $V_{NC} = 2.3 \text{ V}$ ,<br>$V_{COM} = \text{Open}$ ,<br>See <a href="#">Figure 18</a>     | 25°C  | 2.7 V |     | -10   | 0.1   | 10       | nA |
|  |                            |   | Full  |       |     |       | -20   | 20       |    |
| COM ON leakage current                                     | $I_{COM(ON)}$              | $V_{NO}$ or $V_{NC} = \text{Open}$ ,<br>$V_{COM} = 0.3 \text{ V}$ ,<br>or<br>$V_{NO}$ or $V_{NC} = \text{Open}$ ,<br>$V_{COM} = 2.3 \text{ V}$ ,<br>See <a href="#">Figure 18</a>     | 25°C  | 2.7 V |     | -10   | 0.1   | 10       | nA |
|  |                            |   | Full  |       |     |       | -20   | 20       |    |
| <b>Digital Control Inputs (IN1-2, IN3-4)<sup>(2)</sup></b> |                            |   |       |       |     |       |       |          |    |
| Input logic high   | $V_{IH}$                   |   | Full  |       |     | 1.2   | 4.3   | V        |    |
| Input logic low  | $V_{IL}$                   |   | Full  |       |     | 0     | 0.6   | V        |    |
| Input leakage current                                      | $I_{IH}, I_{IL}$           | $V_{IN} = 3.6 \text{ V or } 0$  | 25°C  | 2.7 V |     | 0.5   | 10    | nA       |    |
|  |                            |   | Full  |       |     |       | 50    |          |    |

(1) The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum

(2) All unused digital inputs of the device must be held at  $V_+$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



**ELECTRICAL CHARACTERISTICS FOR 2.5-V SUPPLY (continued)**
 $V_+ = 2.3\text{ V to }2.7\text{ V}$ ,  $T_A = -40^\circ\text{C to }85^\circ\text{C}$  (unless otherwise noted)

| PARAMETER                 | SYMBOL                           | TEST CONDITIONS  | $T_A$ | $V_+$          | MIN   | TYP   | MAX           | UNIT |
|---------------------------|----------------------------------|--|-------|----------------|-------|-------|---------------|------|
| <b>Dynamic</b>            |                                  |  |       |                |       |       |               |      |
| Turn-on time              | $t_{ON}$                         | $V_{COM} = V_+$ ,<br>$R_L = 50\ \Omega$ ,<br>$C_L = 35\text{ pF}$                      | 25°C  | 2.5 V          | 2.6   | 47    | ns            |      |
|                           |                                  |  | Full  | 2.3 V to 2.7 V |       | 50    |               |      |
| Turn-off time             | $t_{OFF}$                        | $V_{COM} = V_+$ ,<br>$R_L = 50\ \Omega$ ,<br>$C_L = 35\text{ pF}$                      | 25°C  | 2.5 V          | 16.5  | 34    | ns            |      |
|                           |                                  |  | Full  | 2.3 V to 2.7 V |       | 35    |               |      |
| Break-before-make time    | $t_{BBM}$                        | $V_{NC} = V_{NO} = V_+$ ,<br>$R_L = 50\ \Omega$ ,<br>$C_L = 35\text{ pF}$              | 25°C  | 2.5 V          | 4     | 15    | 35            | ns   |
|                           |                                  |  | Full  | 2.3 V to 2.7 V | 3     |       | 35            |      |
| Charge injection          | $Q_C$                            | $V_{GEN} = 0$ ,<br>$R_{GEN} = 0$ ,<br>$C_L = 1\text{ nF}$                              | 25°C  | 2.5 V          |       | 84    | pC            |      |
| NC, NO OFF capacitance    | $C_{NC(OFF)}$ ,<br>$C_{NO(OFF)}$ | $V_{NC}$ or $V_{NO} = V_+$ or GND,<br>Switch OFF,<br>See <a href="#">Figure 19</a>     | 25°C  | 2.5 V          |       | 52    | pF            |      |
| NC, NO ON capacitance     | $C_{NC(ON)}$ ,<br>$C_{NO(ON)}$   | $V_{NC}$ or $V_{NO} = V_+$ or GND,<br>Switch OFF,<br>See <a href="#">Figure 19</a>     | 25°C  | 2.5 V          |       | 163   | pF            |      |
| COM ON capacitance        | $C_{COM(ON)}$                    | $V_{COM} = V_+$ or GND,<br>See <a href="#">Figure 19</a>                               | 25°C  | 2.5 V          |       | 163   | pF            |      |
| Digital input capacitance | $C_I$                            | $V_I = V_+$ or GND   | 25°C  | 2.5 V          |       | 2.5   | pF            |      |
| Bandwidth                 | BW                               | $R_L = 50\ \Omega$ ,<br>Switch ON  | 25°C  | 2.5 V          |       | 35    | MHz           |      |
| OFF isolation             | $O_{ISO}$                        | $R_L = 50\ \Omega$ ,<br>$f = 100\text{ kHz}$ ,<br>Switch OFF                           | 25°C  | 2.5 V          |       | -71   | dB            |      |
| Crosstalk                 | $X_{TALK}$                       | $R_L = 50\ \Omega$ ,<br>$f = 100\text{ kHz}$ ,<br>Switch ON                            | 25°C  | 2.5 V          |       | -73   | dB            |      |
| Total harmonic distortion | THD                              | $R_L = 600\ \Omega$ ,<br>$C_L = 50\text{ pF}$ ,<br>$f = 20\text{ Hz to }20\text{ kHz}$ | 25°C  | 2.5 V          |       | 0.009 | %             |      |
| <b>Supply</b>             |                                  |  |       |                |       |       |               |      |
| Positive supply current   | $I_+$                            | $V_I = V_+$ or GND,<br>Switch ON or OFF  | 25°C  | 2.5 V          | 0.004 | 0.1   | $\mu\text{A}$ |      |
|                           |                                  |  | Full  |                |       | 0.5   |               |      |

**ELECTRICAL CHARACTERISTICS FOR 1.8-V SUPPLY<sup>(1)</sup>**
 $V_+ = 1.65\text{ V to }1.95\text{ V}$ ,  $T_A = -40^\circ\text{C to }85^\circ\text{C}$  (unless otherwise noted)

| PARAMETER  | SYMBOL                     | TEST CONDITIONS  | $T_A$                                       | $V_+$ | MIN    | TYP  | MAX   | UNIT     |    |
|--|----------------------------|--|---|-------|--------|------|-------|----------|----|
| <b>Analog Switch</b>                                       |                            |  |   |       |        |      |       |          |    |
| Analog signal range  | $V_{COM}, V_{NO}, V_{NC}$  |  |   |       | 0      |      | $V_+$ | V        |    |
| ON-state resistance  | $r_{on}$                   | $V_{NO}$ or $V_{NC} = 1.5\text{ V}$ ,<br>$I_{COM} = -100\text{ mA}$ ,  | Switch ON,<br>See <a href="#">Figure 16</a> | 25°C  | 1.65 V | 0.5  | 0.7   | $\Omega$ |    |
|  |                            |  |   | Full  |        | 0.8  |       |          |    |
| ON-state resistance match between channels                 | $\Delta r_{on}$            | $V_{NO}$ or $V_{NC} = 1.5\text{ V}$ , 0.6 V<br>$I_{COM} = -100\text{ mA}$ ,  | Switch ON,<br>See <a href="#">Figure 16</a> | 25°C  | 1.65 V | 0.05 | 0.07  | $\Omega$ |    |
|  |                            |  |   | Full  |        | 0.1  |       |          |    |
| ON-state resistance flatness                               | $r_{on(Flat)}$             | $V_{NO}$ or $V_{NC} = 1.5\text{ V}$ , 0.6 V<br>1.5 V, 2.5 V,<br>$I_{COM} = -100\text{ mA}$ ,   | Switch ON,<br>See <a href="#">Figure 16</a> | 25°C  | 1.65 V | 0.5  | 0.7   | $\Omega$ |    |
|  |                            |  |   | Full  |        | 0.8  |       |          |    |
| NC, NO OFF leakage current                                 | $I_{NO(OFF)}, I_{NC(OFF)}$ | $V_{NO}$ or $V_{NC} = 0.3\text{ V}$ ,<br>$V_{COM} = 1.65\text{ V}$ ,<br>or<br>$V_{NO}$ or $V_{NC} = 1.65\text{ V}$ ,<br>$V_{COM} = 0.3\text{ V}$ , | See <a href="#">Figure 17</a>               | 25°C  | 1.95 V | -10  | 0.5   | 10       | nA |
|  |                            |  |   | Full  |        | -20  | 20    |          |    |
| NC, NO ON leakage current                                  | $I_{NO(ON)}, I_{NC(ON)}$   | $V_{NO}$ or $V_{NC} = 0.3\text{ V}$ ,<br>$V_{COM} = \text{Open}$ ,<br>or<br>$V_{NO}$ or $V_{NC} = 1.65\text{ V}$ ,<br>$V_{COM} = \text{Open}$ ,    | See <a href="#">Figure 18</a>               | 25°C  | 1.95 V | -10  | 0.1   | 10       | nA |
|  |                            |  |   | Full  |        | -20  | 20    |          |    |
| COM ON leakage current                                     | $I_{COM(ON)}$              | $V_{NO}$ or $V_{NC} = \text{Open}$ ,<br>$V_{COM} = 0.3\text{V}$ ,<br>or<br>$V_{NO}$ or $V_{NC} = \text{Open}$ ,<br>$V_{COM} = 1.65\text{ V}$ ,     | See <a href="#">Figure 18</a>               | 25°C  | 1.95 V | -10  | 0.1   | 10       | nA |
|  |                            |  |   | Full  |        | -20  | 20    |          |    |
| <b>Digital Control Inputs (IN1-2, IN3-4)<sup>(2)</sup></b> |                            |  |   |       |        |      |       |          |    |
| Input logic high   | $V_{IH}$                   |  | Full  |       | 1      |      | 4.3   | V        |    |
| Input logic low  | $V_{IL}$                   |  | Full  |       | 0      |      | 0.4   | V        |    |
| Input leakage current                                      | $I_{IH}, I_{IL}$           | $V_{IN} = 3.6\text{ V or }0$   |   | 25°C  | 1.95 V | 0.5  | 10    | nA       |    |
|  |                            |  |   | Full  |        | 50   |       |          |    |

(1) The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum

(2) All unused digital inputs of the device must be held at  $V_+$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

**ELECTRICAL CHARACTERISTICS FOR 1.8-V SUPPLY (continued)**
 $V_+ = 1.65\text{ V to }1.95\text{ V}$ ,  $T_A = -40^\circ\text{C to }85^\circ\text{C}$  (unless otherwise noted)

| PARAMETER                    | SYMBOL                           | TEST CONDITIONS  | $T_A$ | $V_+$               | MIN | TYP   | MAX  | UNIT          |
|------------------------------|----------------------------------|--|-------|---------------------|-----|-------|------|---------------|
| <b>Dynamic</b>               |                                  |  |       |                     |     |       |      |               |
| Turn-on time                 | $t_{ON}$                         | $V_{COM} = V_+$ ,<br>$R_L = 50\ \Omega$ ,<br>$C_L = 35\text{ pF}$                      | 25°C  | 1.8 V               |     | 40    | 70   | ns            |
|                              |                                  |  | Full  | 1.65 V to<br>1.95 V |     |       | 75   |               |
| Turn-off time                | $t_{OFF}$                        | $V_{COM} = V_+$ ,<br>$R_L = 50\ \Omega$ ,<br>$C_L = 35\text{ pF}$                      | 25°C  | 1.8 V               |     | 22    | 45   | ns            |
|                              |                                  |  | Full  | 1.65 V to<br>1.95 V |     |       | 50   |               |
| Break-before-make time       | $t_{BBM}$                        | $V_{NC} = V_{NO} = V_+$ ,<br>$R_L = 50\ \Omega$ ,<br>$C_L = 35\text{ pF}$              | 25°C  | 1.8 V               | 5   | 25    | 70   | ns            |
|                              |                                  |  | Full  | 1.65 V to<br>1.95 V | 4   |       | 75   |               |
| Charge injection             | $Q_C$                            | $V_{GEN} = 0$ ,<br>$R_{GEN} = 0$ ,<br>$C_L = 1\text{ nF}$                              | 25°C  | 1.8 V               |     | 64    |      | pC            |
| NC, NO<br>OFF capacitance    | $C_{NC(OFF)}$ ,<br>$C_{NO(OFF)}$ | $V_{NC}$ or $V_{NO} = V_+$ or GND,<br>Switch OFF,<br>See <a href="#">Figure 19</a>     | 25°C  | 1.8 V               |     | 52    |      | pF            |
| NC, NO<br>ON capacitance     | $C_{NC(ON)}$ ,<br>$C_{NO(ON)}$   | $V_{NC}$ or $V_{NO} = V_+$ or GND,<br>Switch OFF,<br>See <a href="#">Figure 19</a>     | 25°C  | 1.8 V               |     | 164   |      | pF            |
| COM<br>ON capacitance        | $C_{COM(ON)}$                    | $V_{COM} = V_+$ or GND,<br>Switch ON,<br>See <a href="#">Figure 19</a>                 | 25°C  | 1.8 V               |     | 164   |      | pF            |
| Digital input<br>capacitance | $C_I$                            | $V_I = V_+$ or GND   | 25°C  | 1.8 V               |     | 2.5   |      | pF            |
| Bandwidth                    | BW                               | $R_L = 50\ \Omega$ ,<br>Switch ON  | 25°C  | 1.8 V               |     | 35    |      | MHz           |
| OFF isolation                | $O_{ISO}$                        | $R_L = 50\ \Omega$ ,<br>$f = 100\text{ kHz}$ ,<br>Switch OFF                           | 25°C  | 1.8 V               |     | -71   |      | dB            |
| Crosstalk                    | $X_{TALK}$                       | $R_L = 50\ \Omega$ ,<br>$f = 100\text{ kHz}$ ,<br>Switch ON                            | 25°C  | 1.8 V               |     | -73   |      | dB            |
| Total harmonic<br>distortion | THD                              | $R_L = 600\ \Omega$ ,<br>$C_L = 50\text{ pF}$ ,<br>$f = 20\text{ Hz to }20\text{ kHz}$ | 25°C  | 1.8 V               |     | 0.1   |      | %             |
| <b>Supply</b>                |                                  |  |       |                     |     |       |      |               |
| Positive supply<br>current   | $I_+$                            | $V_I = V_+$ or GND,<br>Switch ON or OFF  | 25°C  | 1.95 V              |     | 0.001 | 0.05 | $\mu\text{A}$ |
|                              |                                  |  | Full  |                     |     |       | 0.15 |               |

TYPICAL PERFORMANCE

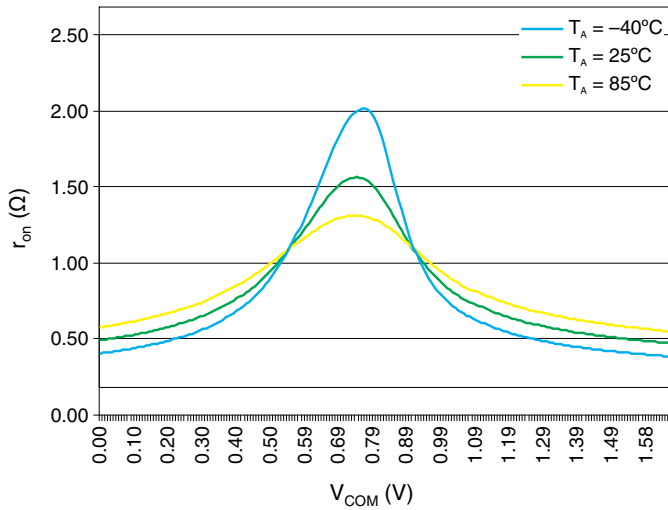


Figure 1.  $r_{on}$  vs  $V_{COM}$  ( $V_+ = 1.65$  V)

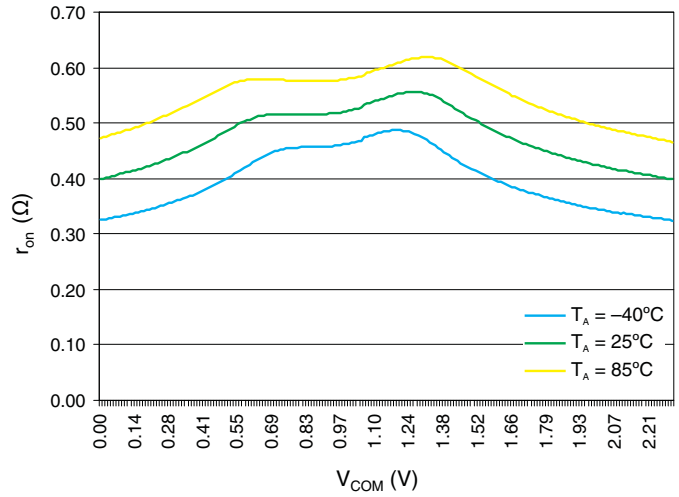


Figure 2.  $r_{on}$  vs  $V_{COM}$  ( $V_+ = 2.3$  V)

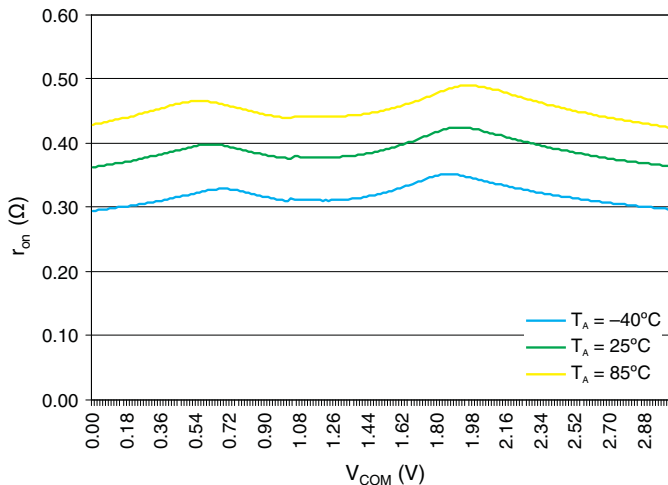


Figure 3.  $r_{on}$  vs  $V_{COM}$  ( $V_+ = 3$  V)

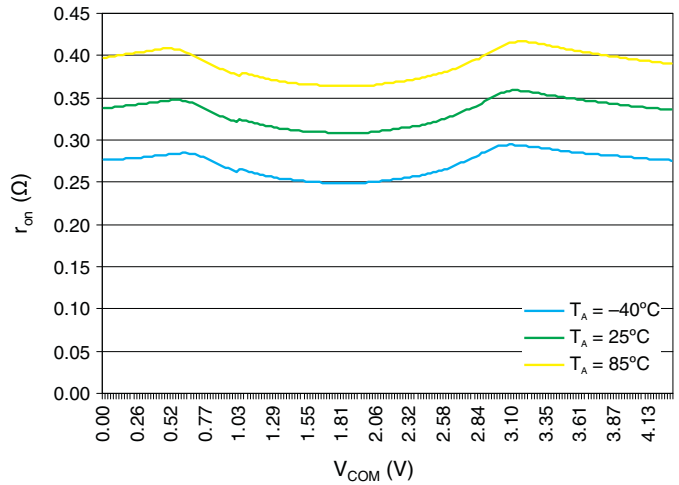


Figure 4.  $r_{on}$  vs  $V_{COM}$  ( $V_+ = 4.3$  V)

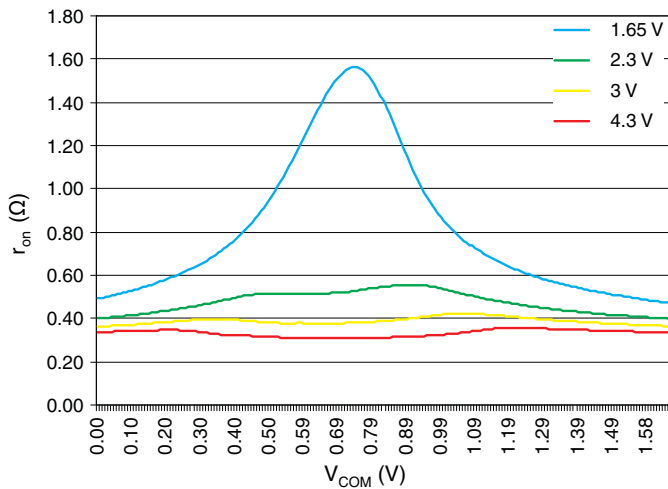


Figure 5.  $r_{on}$  vs  $V_{COM}$  (All Voltages)

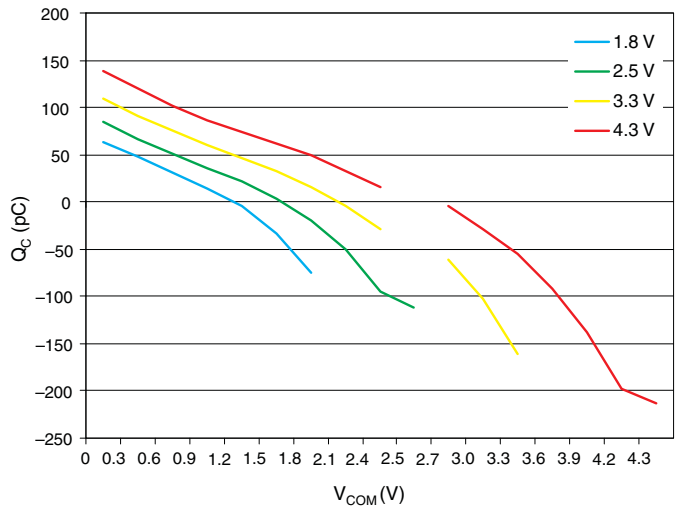


Figure 6. Charge Injection ( $Q_C$ ) vs  $V_{COM}$  ( $T_A = 25^\circ\text{C}$ )

TYPICAL PERFORMANCE (continued)

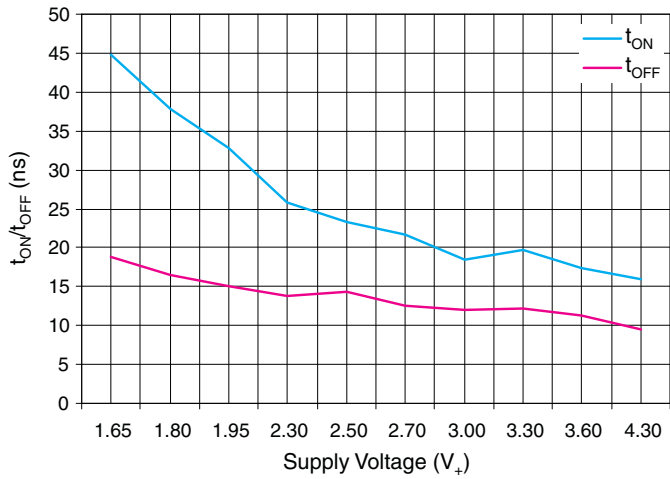


Figure 7. t<sub>ON</sub> and t<sub>OFF</sub> vs Supply Voltage (T<sub>A</sub> = 25°C)

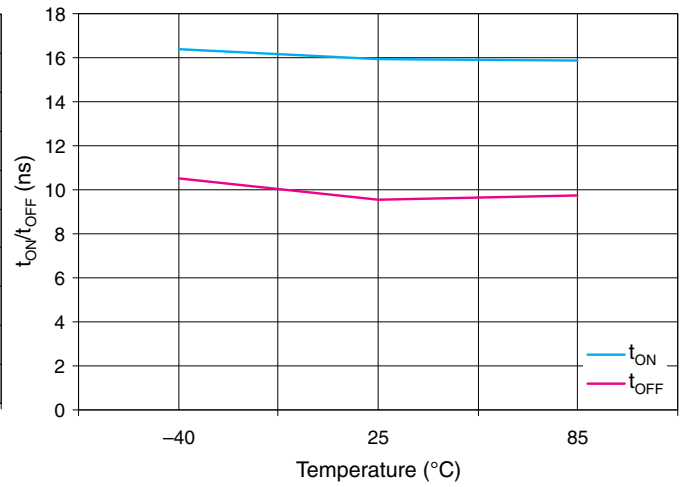


Figure 8. t<sub>ON</sub> and t<sub>OFF</sub> vs Temperature (V<sub>+</sub> = 4.3 V)

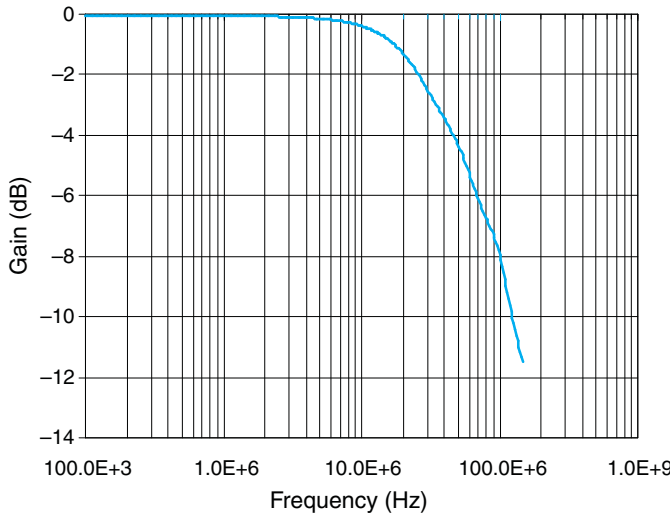


Figure 9. Bandwidth

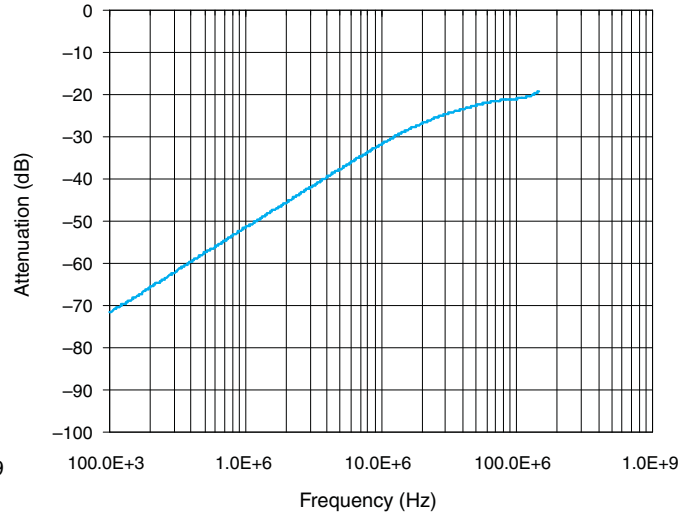


Figure 10. OFF Isolation

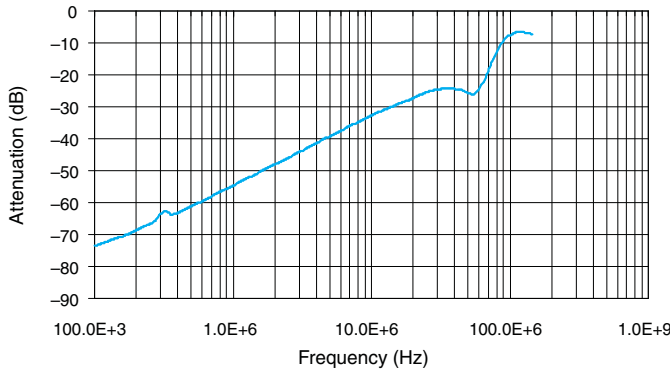


Figure 11. Crosstalk

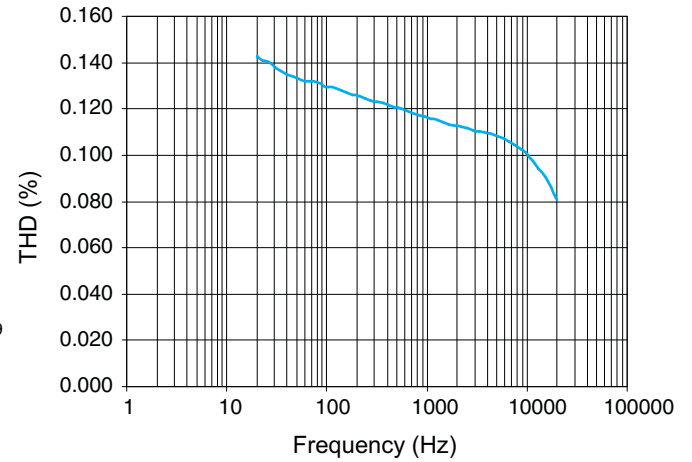
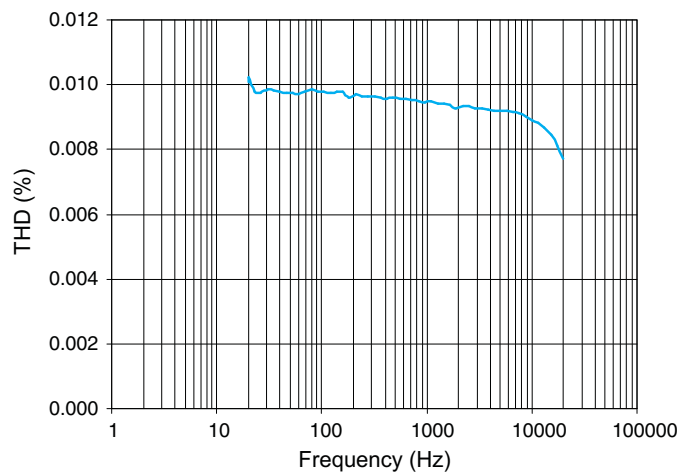
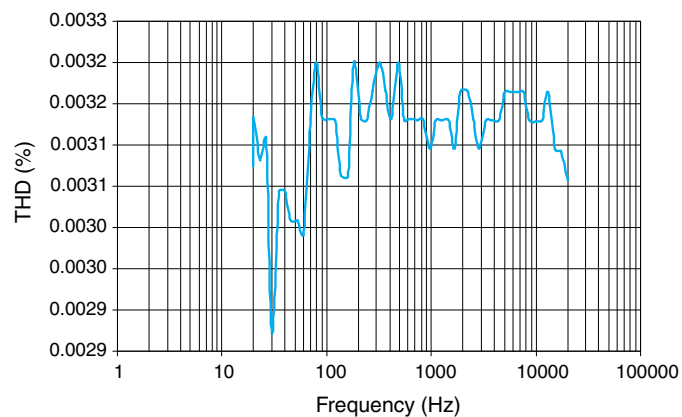


Figure 12. Total Harmonic Distortion vs Frequency (V<sub>+</sub> = 1.8 V)

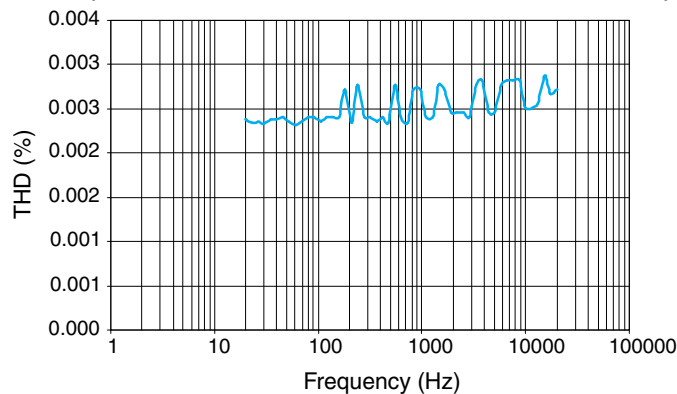
**TYPICAL PERFORMANCE (continued)**



**Figure 13. Total Harmonic Distortion vs Frequency**  
( $V_+ = 2.5\text{ V}$ )



**Figure 14. Total Harmonic Distortion vs Frequency**  
( $V_+ = 3.3\text{ V}$ )



**Figure 15. Total Harmonic Distortion vs Frequency**  
( $V_+ = 4.3\text{ V}$ )

PARAMETER MEASUREMENT INFORMATION

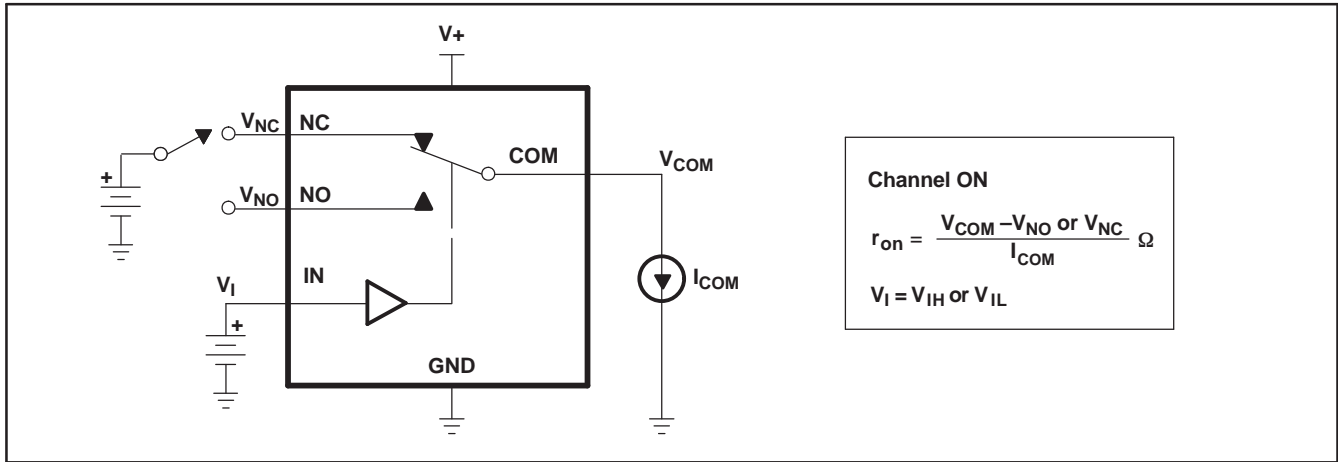


Figure 16. ON-state Resistance ( $r_{ON}$ )

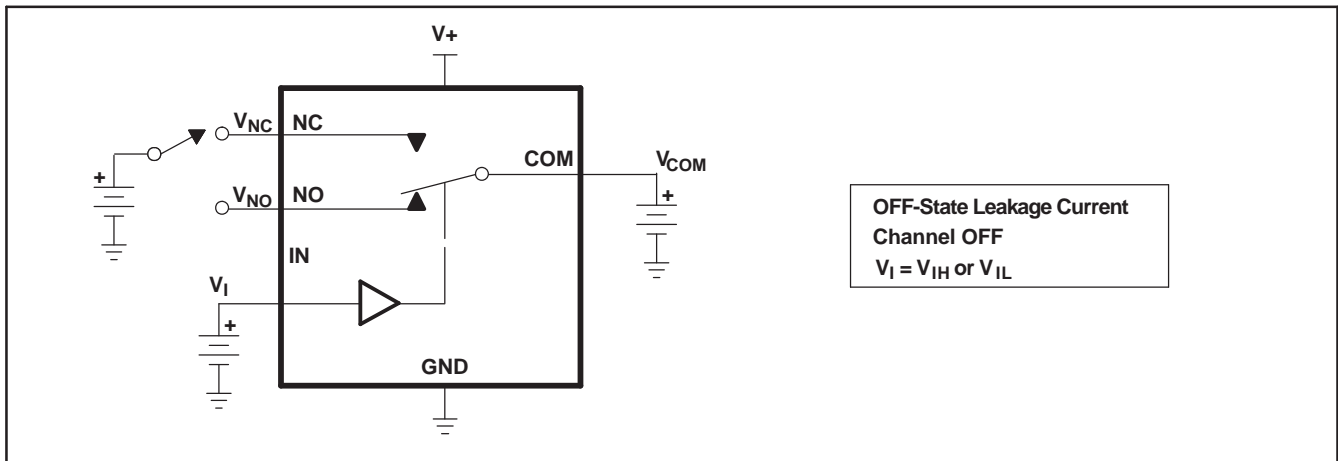


Figure 17. OFF-State Leakage Current  
( $I_{NC(OFF)}$ ,  $I_{NC(PWROFF)}$ ,  $I_{NO(OFF)}$ ,  $I_{NO(PWROFF)}$ ,  $I_{COM(OFF)}$ ,  $I_{COM(PWROFF)}$ )

PARAMETER MEASUREMENT INFORMATION (continued)

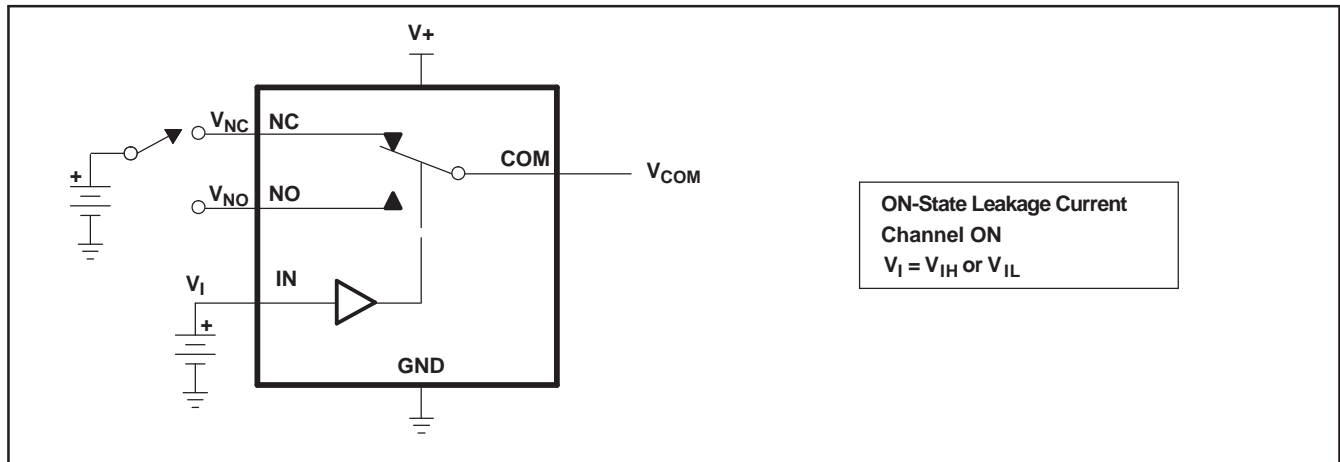


Figure 18. ON-State Leakage Current  
( $I_{COM(ON)}$ ,  $I_{NC(ON)}$ ,  $I_{NO(ON)}$ )

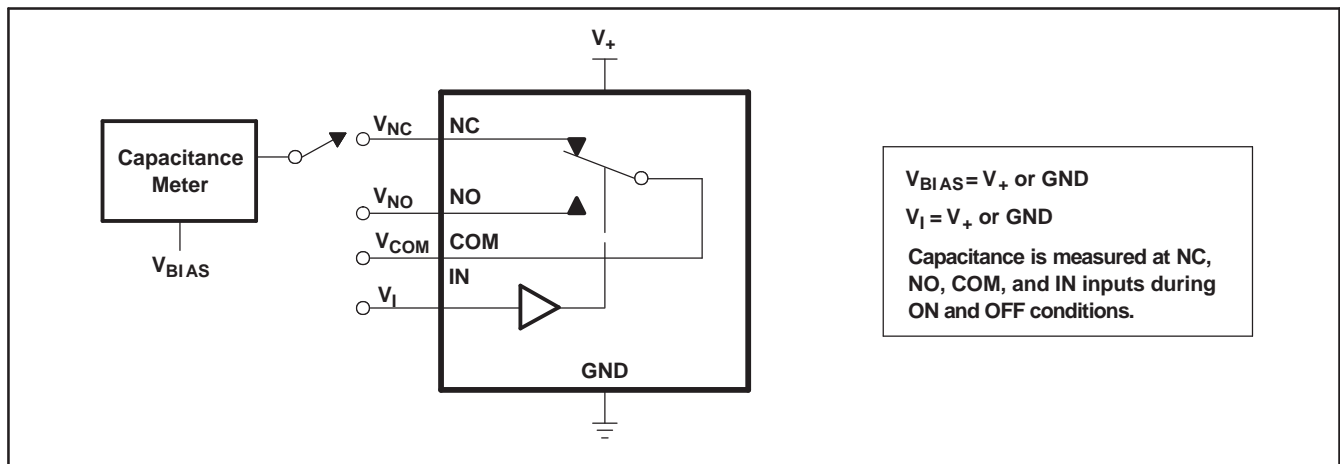
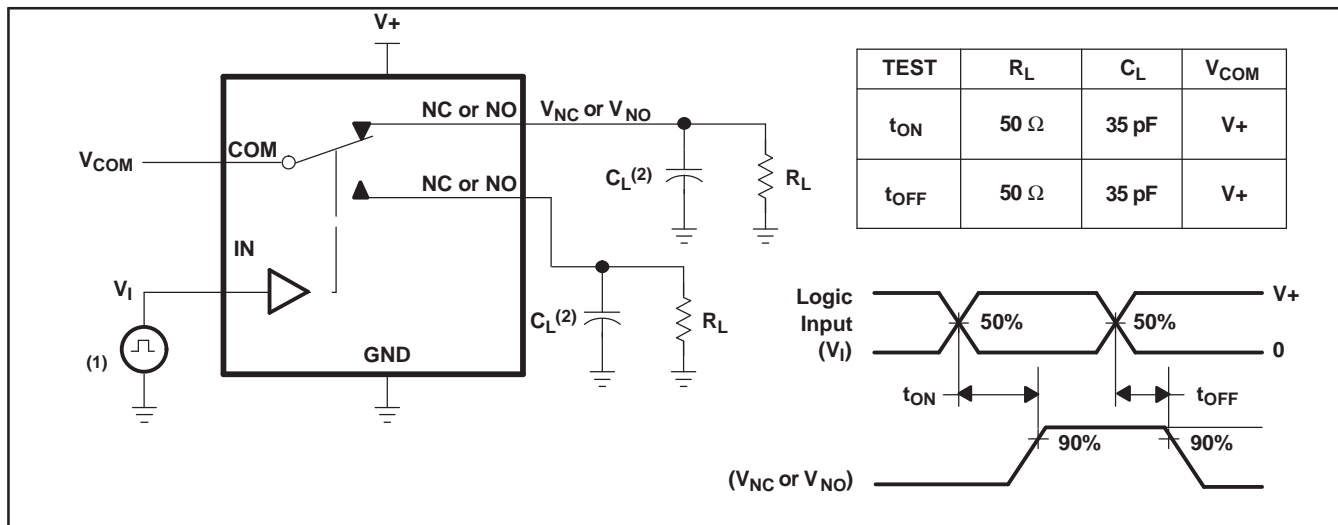


Figure 19. Capacitance  
( $C_I$ ,  $C_{COM(ON)}$ ,  $C_{NC(OFF)}$ ,  $C_{NO(OFF)}$ ,  $C_{NC(ON)}$ ,  $C_{NO(ON)}$ )

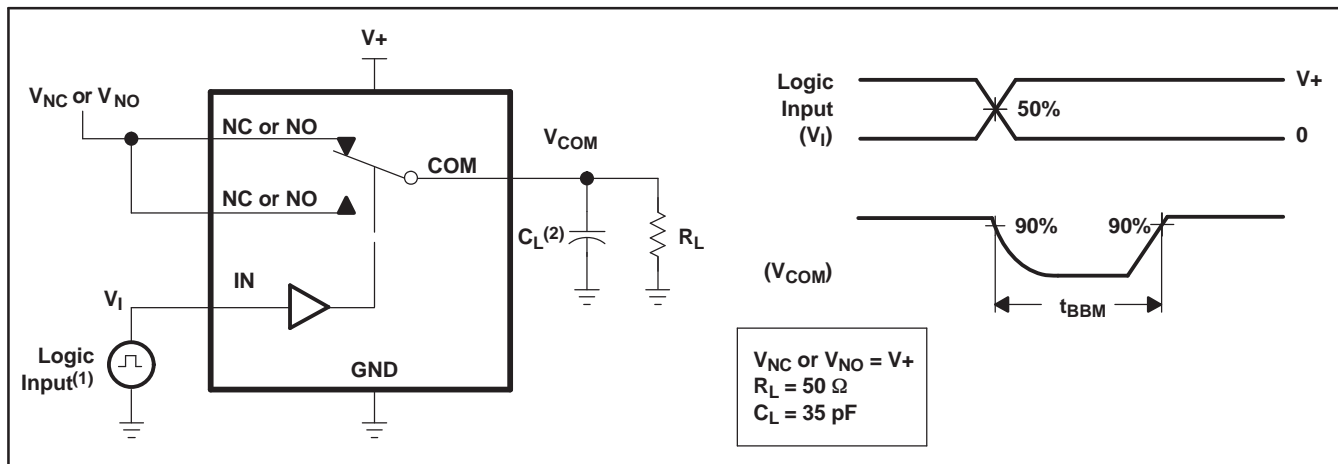


PARAMETER MEASUREMENT INFORMATION (continued)



- A. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ ,  $t_r < 5$  ns,  $t_f < 5$  ns.
- B.  $C_L$  includes probe and jig capacitance.

Figure 20. Turn-On ( $t_{ON}$ ) and Turn-Off Time ( $t_{OFF}$ )



- A.  $C_L$  includes probe and jig capacitance.
- B. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ ,  $t_r < 5$  ns,  $t_f < 5$  ns.

Figure 21. Break-Before-Make Time ( $t_{BBM}$ )

PARAMETER MEASUREMENT INFORMATION (continued)

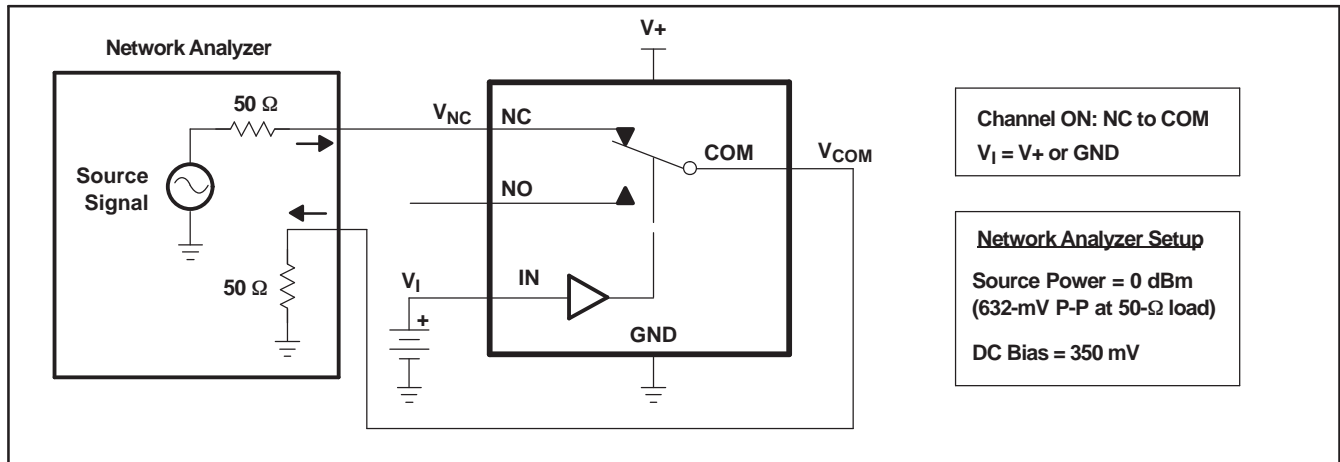


Figure 22. Bandwidth (BW)

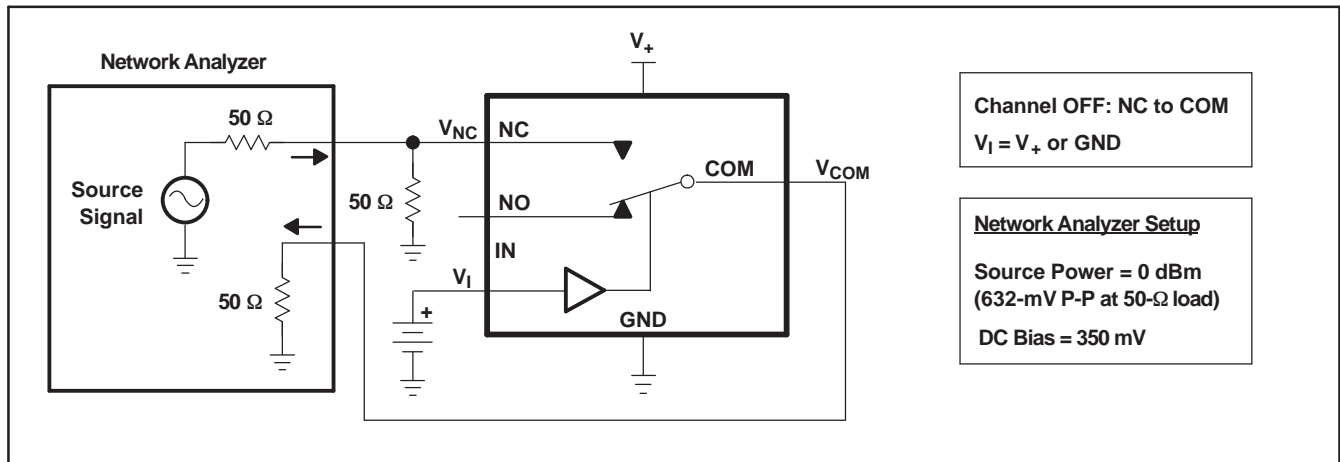


Figure 23. OFF Isolation ( $O_{ISO}$ )

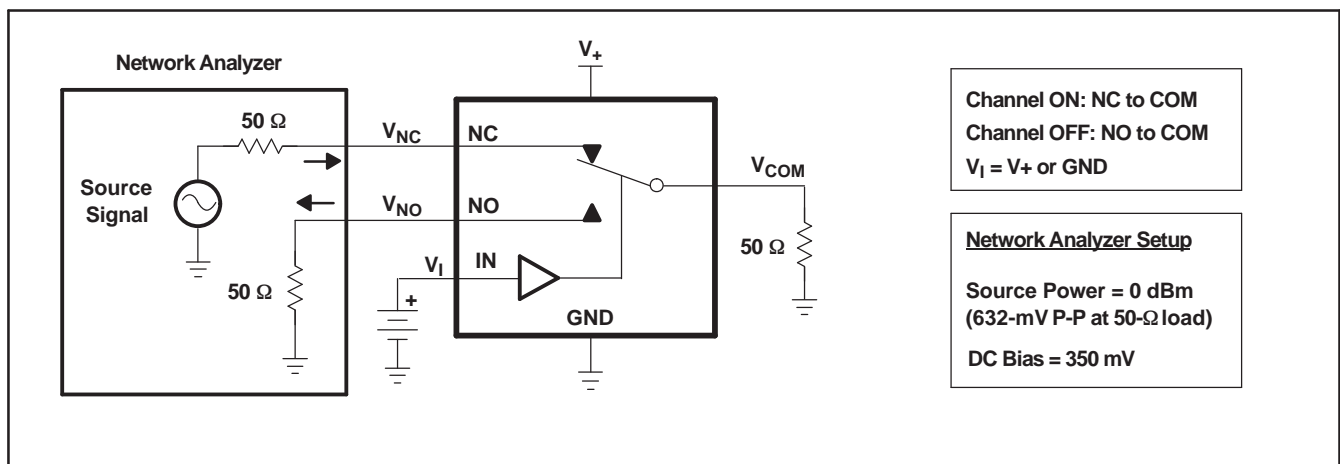
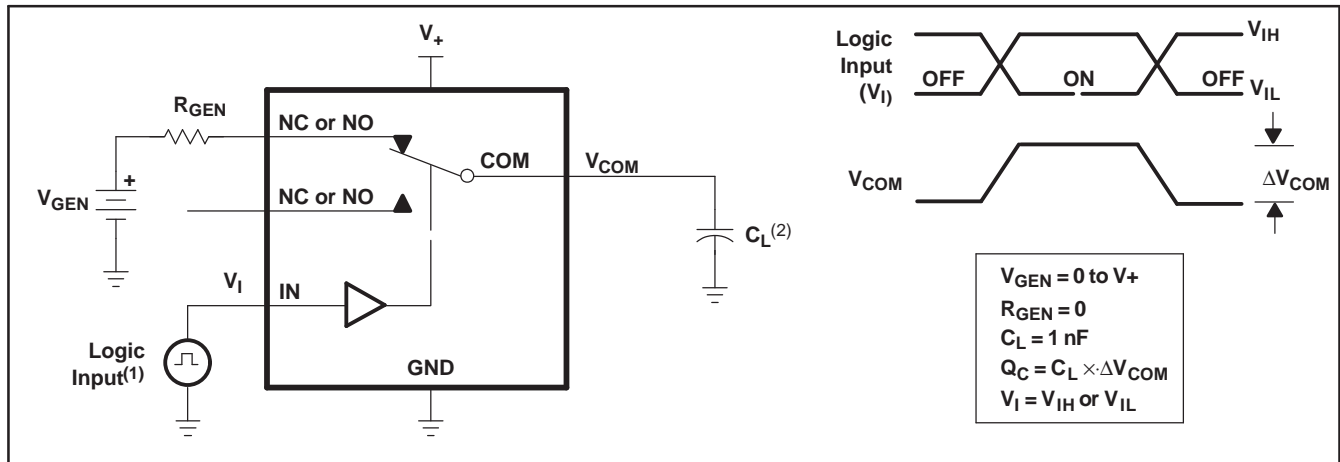


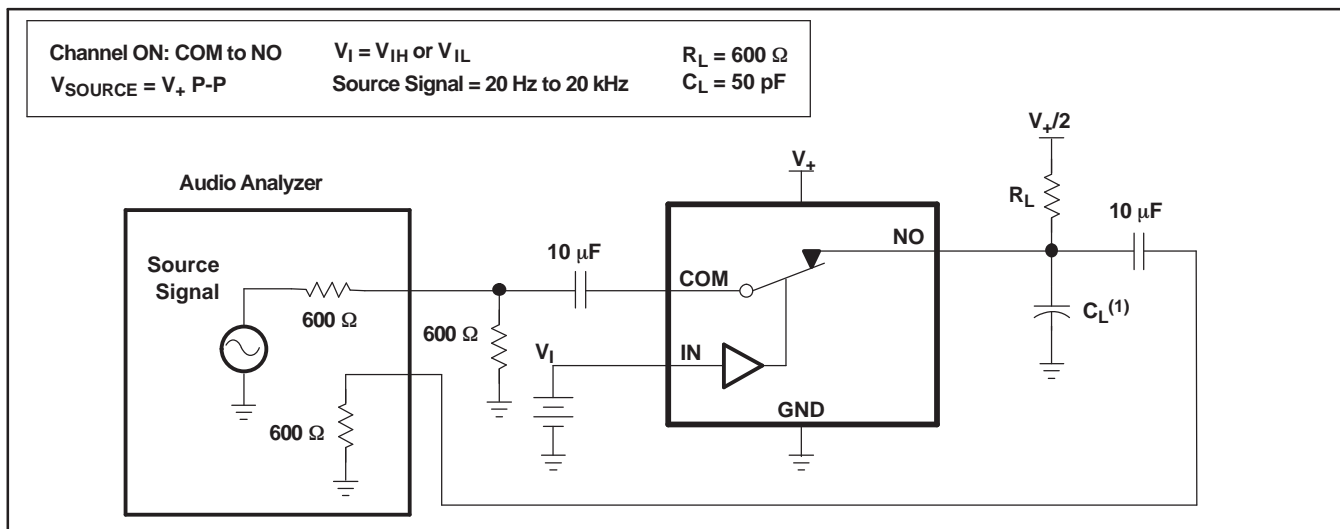
Figure 24. Crosstalk ( $X_{TALK}$ )

PARAMETER MEASUREMENT INFORMATION (continued)



- A. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z<sub>O</sub> = 50 Ω, t<sub>r</sub> < 5 ns, t<sub>f</sub> < 5 ns.
- B. C<sub>L</sub> includes probe and jig capacitance.

Figure 25. Charge Injection (Q<sub>C</sub>)



- A. C<sub>L</sub> includes probe and jig capacitance.

Figure 26. Total Harmonic Distortion (THD)

## PACKAGING INFORMATION

| Orderable Device | Status<br>(1) | Package Type | Package<br>Drawing | Pins | Package Qty | Eco Plan<br>(2)            | Lead/Ball Finish | MSL Peak Temp<br>(3) | Op Temp (°C) | Top-Side Markings<br>(4) | Samples                 |
|------------------|---------------|--------------|--------------------|------|-------------|----------------------------|------------------|----------------------|--------------|--------------------------|-------------------------|
| TS3A44159PWR     | ACTIVE        | TSSOP        | PW                 | 16   | 2000        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM   | -40 to 85    | YC4159                   | <a href="#">Samples</a> |
| TS3A44159PWRG4   | ACTIVE        | TSSOP        | PW                 | 16   | 2000        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM   | -40 to 85    | YC4159                   | <a href="#">Samples</a> |
| TS3A44159RGTR    | ACTIVE        | QFN          | RGT                | 16   | 3000        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM   | -40 to 85    | ZWH                      | <a href="#">Samples</a> |
| TS3A44159RGTRG4  | ACTIVE        | QFN          | RGT                | 16   | 3000        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM   | -40 to 85    | ZWH                      | <a href="#">Samples</a> |
| TS3A44159RSVR    | ACTIVE        | UQFN         | RSV                | 16   | 3000        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM   | -40 to 85    | ZWH                      | <a href="#">Samples</a> |
| TS3A44159RSVRG4  | ACTIVE        | UQFN         | RSV                | 16   | 3000        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM   | -40 to 85    | ZWH                      | <a href="#">Samples</a> |

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Only one of markings shown within the brackets will appear on the physical device.

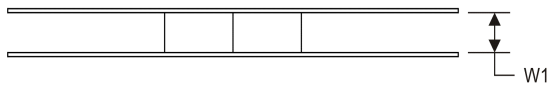
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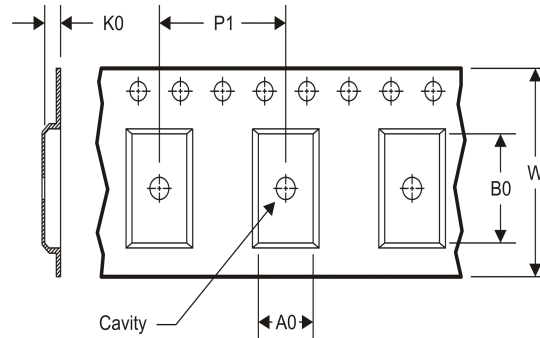
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**TAPE AND REEL INFORMATION**

**REEL DIMENSIONS**



**TAPE DIMENSIONS**



|    |   |
|----|---|
| A0 | Dimension designed to accommodate the component width     |
| B0 | Dimension designed to accommodate the component length    |
| K0 | Dimension designed to accommodate the component thickness |
| W  | Overall width of the carrier tape                         |
| P1 | Pitch between successive cavity centers                   |

**TAPE AND REEL INFORMATION**

\*All dimensions are nominal

| Device        | Package Type | Package Drawing | Pins | SPQ  | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|---------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| TS3A44159PWR  | TSSOP        | PW              | 16   | 2000 | 330.0              | 12.4               | 6.9     | 5.6     | 1.6     | 8.0     | 12.0   | Q1            |
| TS3A44159RGTR | QFN          | RGT             | 16   | 3000 | 330.0              | 12.4               | 3.3     | 3.3     | 1.0     | 8.0     | 12.0   | Q2            |
| TS3A44159RSVR | UQFN         | RSV             | 16   | 3000 | 177.8              | 12.4               | 2.0     | 2.8     | 0.7     | 4.0     | 12.0   | Q1            |

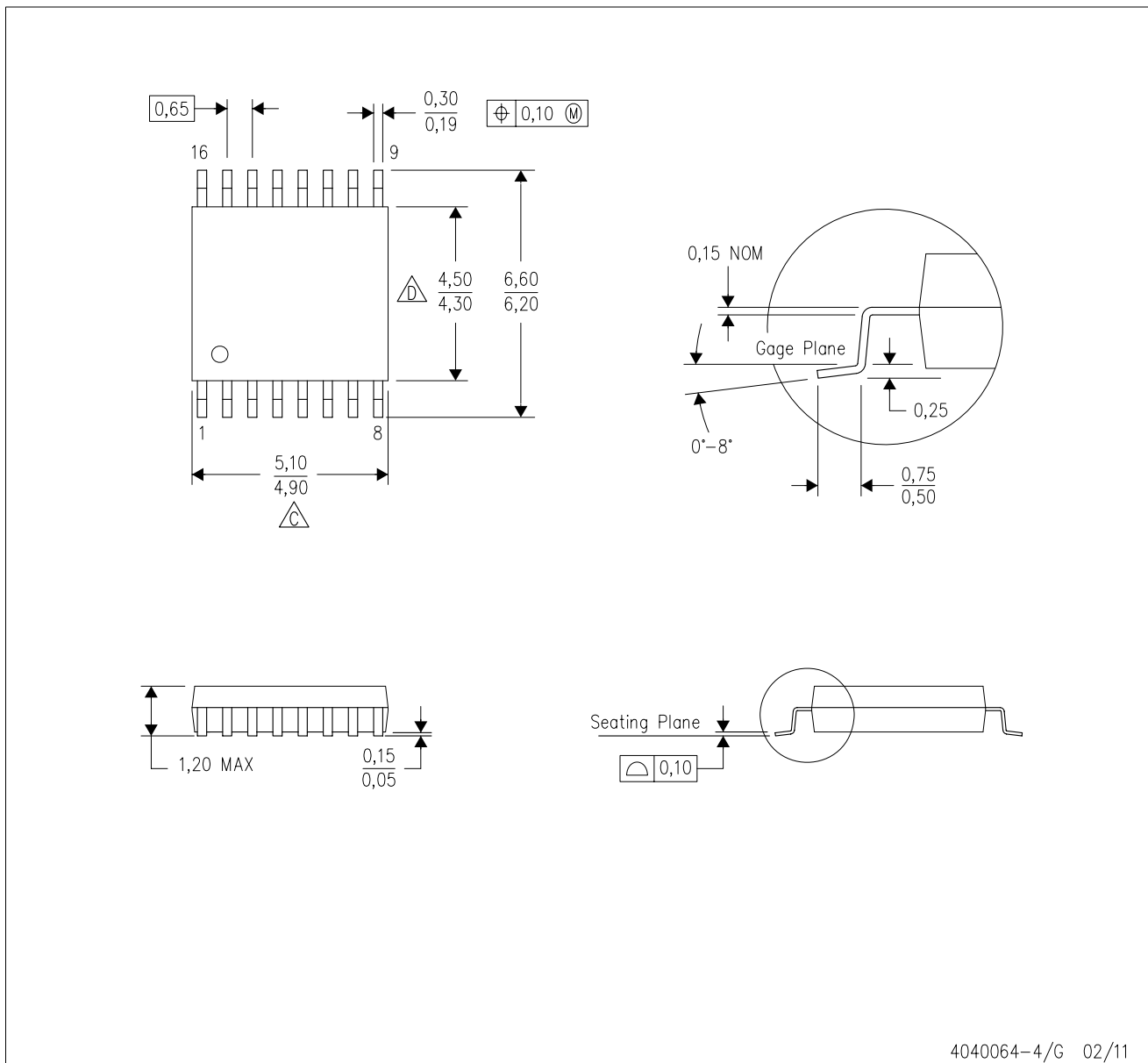
**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

| Device        | Package Type | Package Drawing | Pins | SPQ  | Length (mm) | Width (mm) | Height (mm) |
|---------------|--------------|-----------------|------|------|-------------|------------|-------------|
| TS3A44159PWR  | TSSOP        | PW              | 16   | 2000 | 367.0       | 367.0      | 35.0        |
| TS3A44159RGTR | QFN          | RGT             | 16   | 3000 | 346.0       | 346.0      | 35.0        |
| TS3A44159RSVR | UQFN         | RSV             | 16   | 3000 | 202.0       | 201.0      | 28.0        |

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



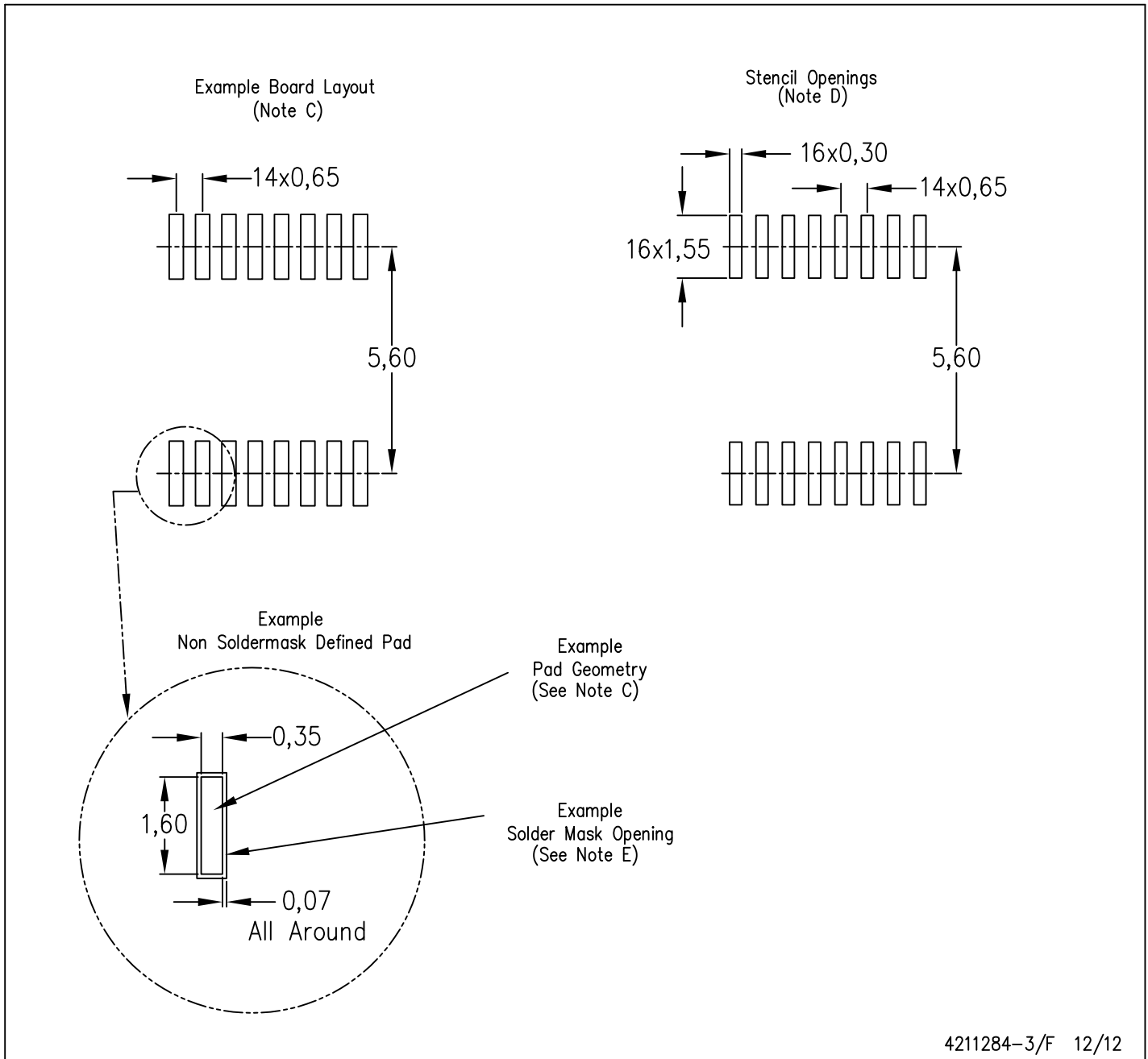
4040064-4/G 02/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
  - E. Falls within JEDEC MO-153



PW (R-PDSO-G16)

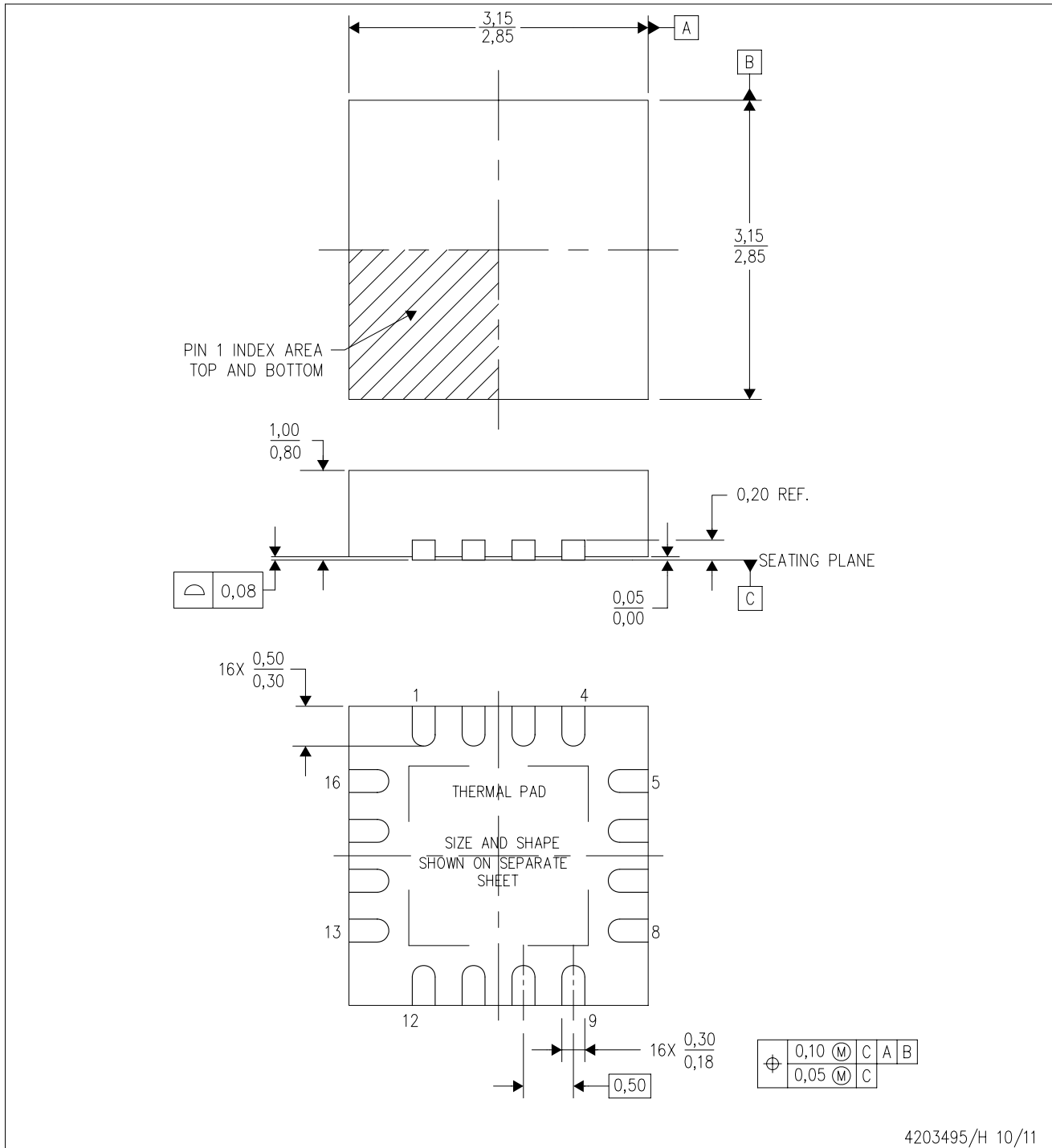
PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

RGT (S-PVQFN-N16)

PLASTIC QUAD FLATPACK NO-LEAD



4203495/H 10/11

- NOTES:
- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - This drawing is subject to change without notice.
  - Quad Flatpack, No-leads (QFN) package configuration.
  - The package thermal pad must be soldered to the board for thermal and mechanical performance.
  - See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
  - Falls within JEDEC MO-220.

## THERMAL PAD MECHANICAL DATA

RGT (S-PVQFN-N16)

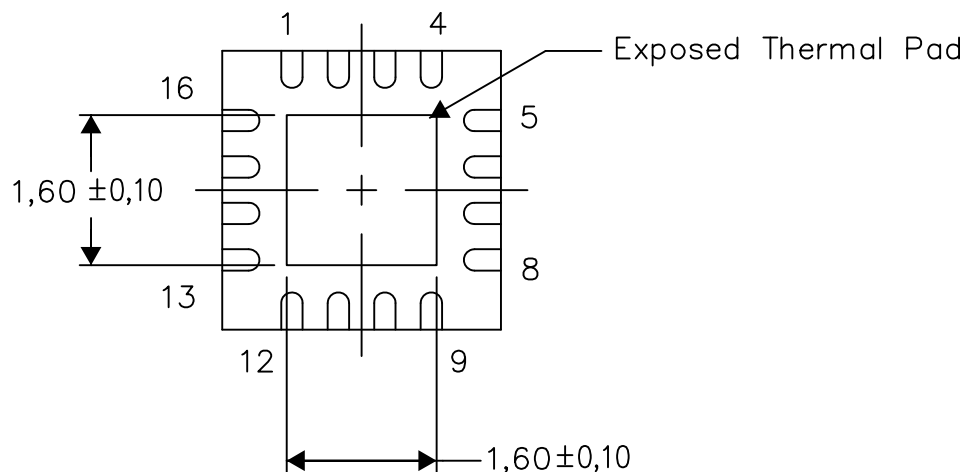
PLASTIC QUAD FLATPACK NO-LEAD

### THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at [www.ti.com](http://www.ti.com).

The exposed thermal pad dimensions for this package are shown in the following illustration.



Bottom View

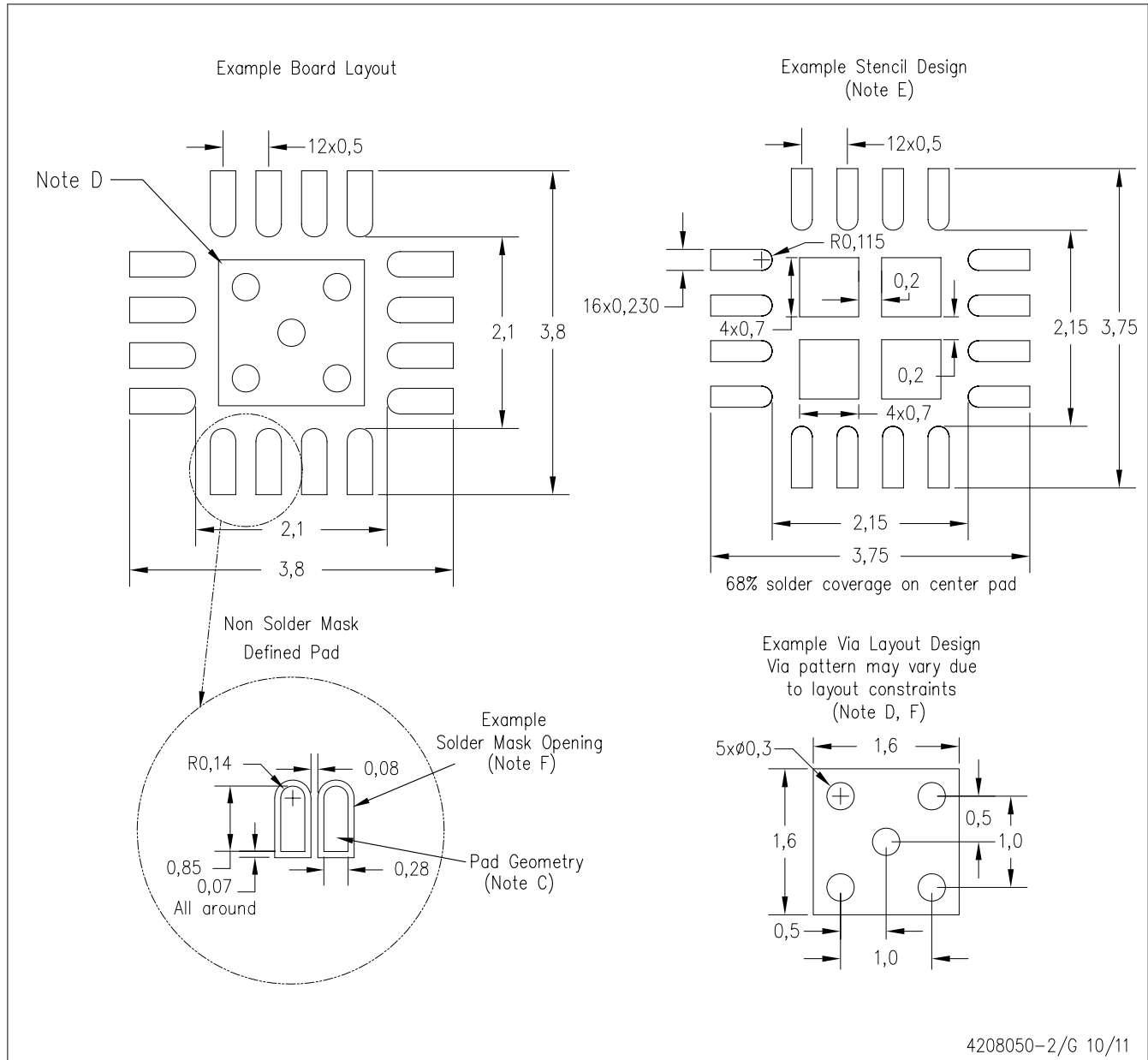
Exposed Thermal Pad Dimensions

4206349-3/R 12/12

NOTE: All linear dimensions are in millimeters

RGT (S-PVQFN-N16)

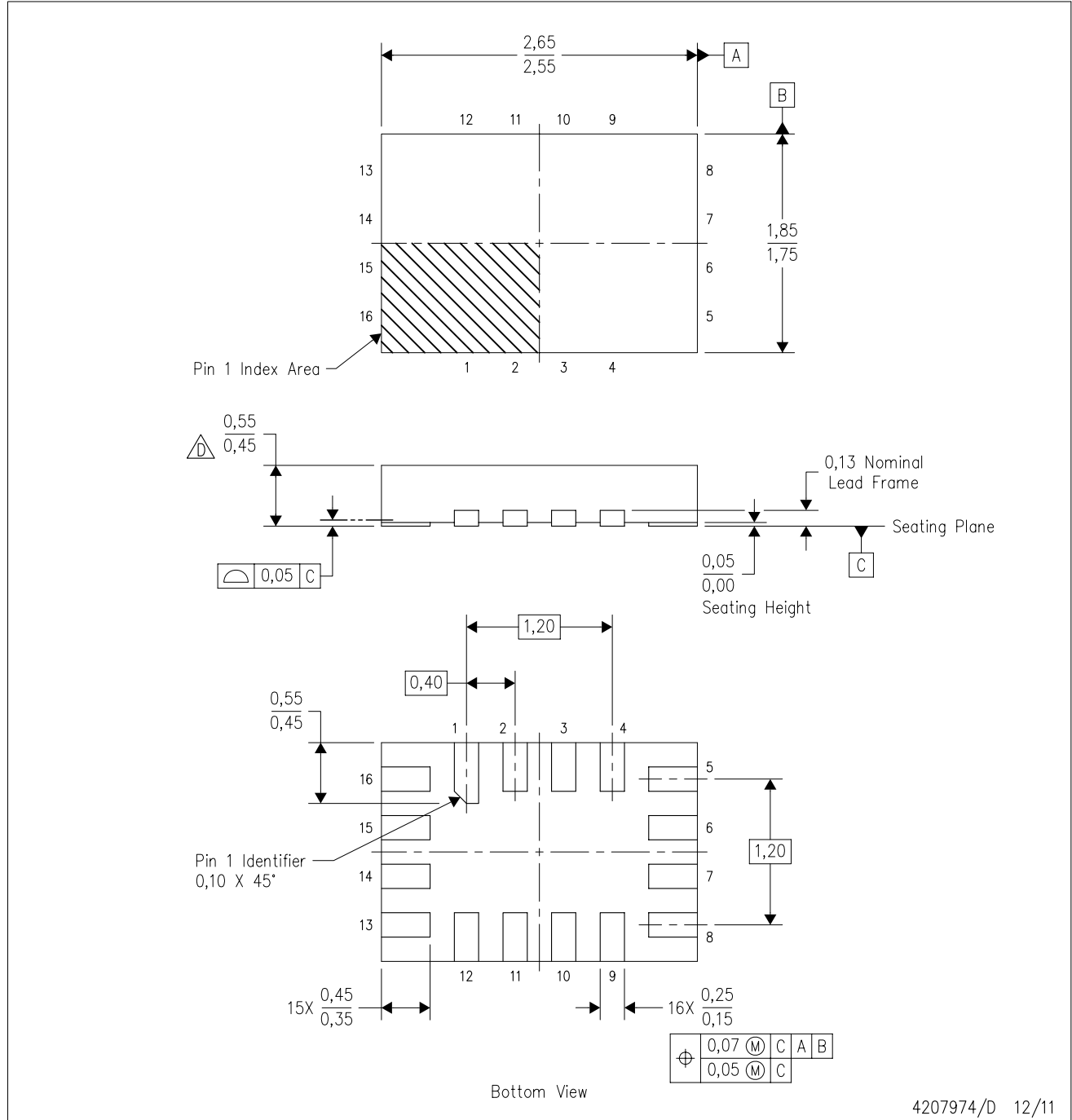
PLASTIC QUAD FLATPACK NO-LEAD




- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at [www.ti.com](http://www.ti.com) <<http://www.ti.com>>.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
  - Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.

RSV (R-PUQFN-N16)

PLASTIC QUAD FLATPACK NO-LEAD

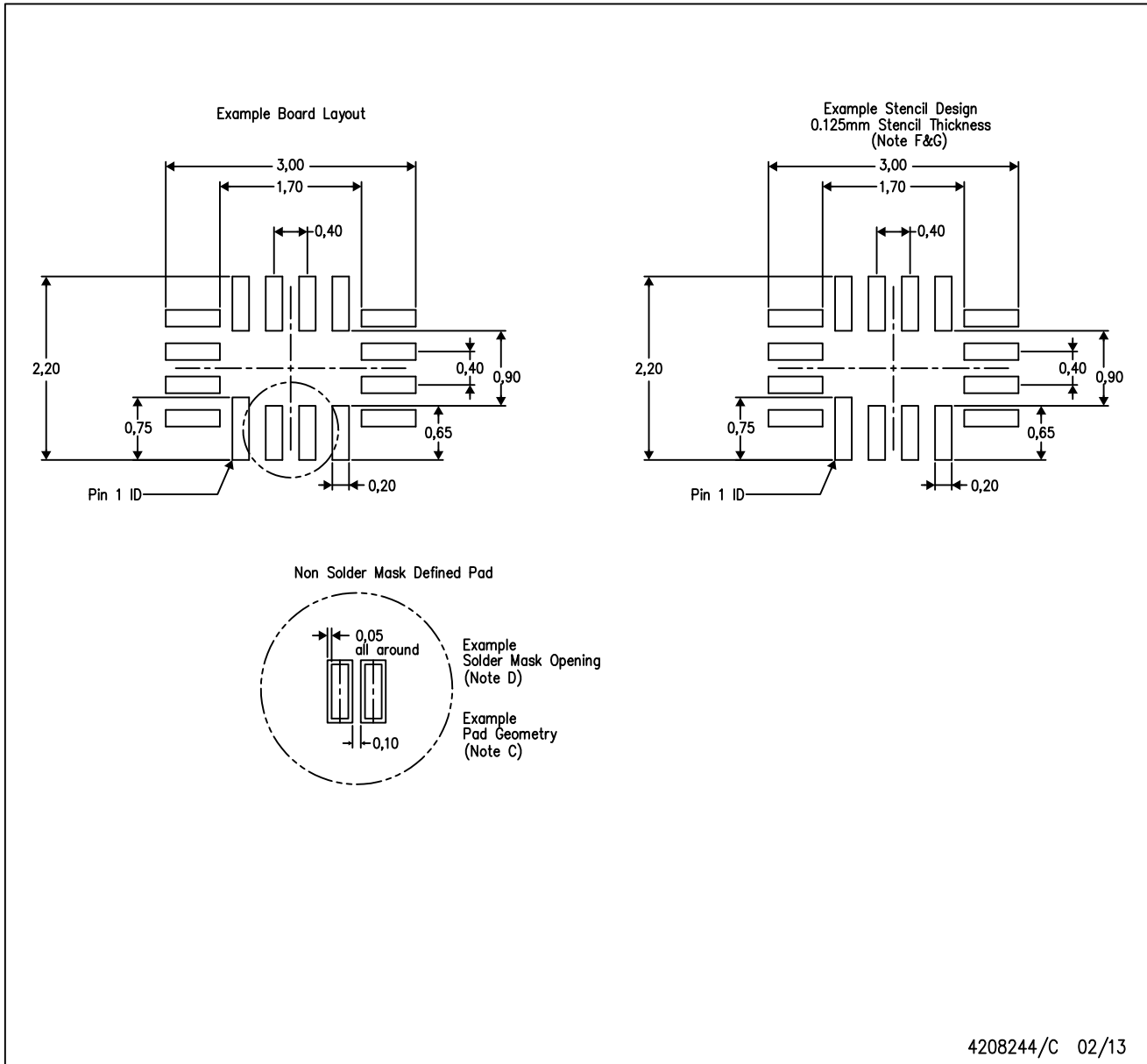


4207974/D 12/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. QFN (Quad Flatpack No-Lead) package configuration.
  -  This package complies to JEDEC MO-288 variation UFHE, except minimum package thickness.

RSV (R-PUQFN-N16)

PLASTIC QUAD FLATPACK NO-LEAD



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.
  - Maximum stencil thickness 0,127 mm (5 mils). All linear dimensions are in millimeters.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
  - Side aperture dimensions over-print land for acceptable area ratio > 0.66. Customer may reduce side aperture dimensions if stencil manufacturing process allows for sufficient release at smaller opening.

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